

Webinar Series in TEM: Sample Preparation

Non-Biological Samples

Riza Iskandar

Customer Success Manager

Material and Structural Analysis - APAC



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PENGEMBANGAN

LabTEM
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TEM Sample Preparation – Non-Biological Sample

Outline

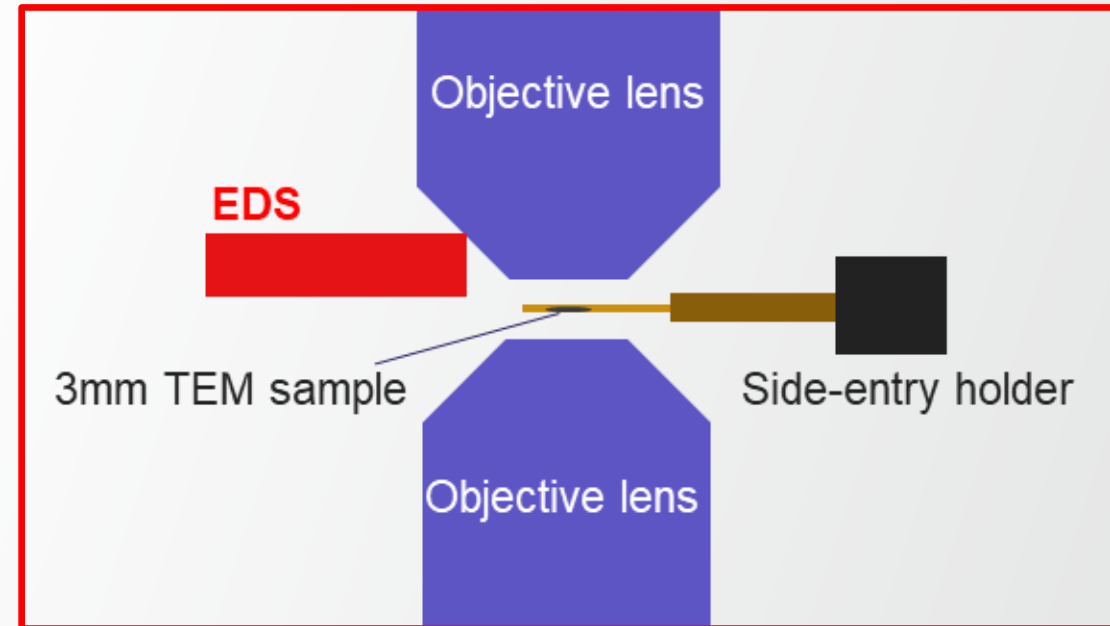
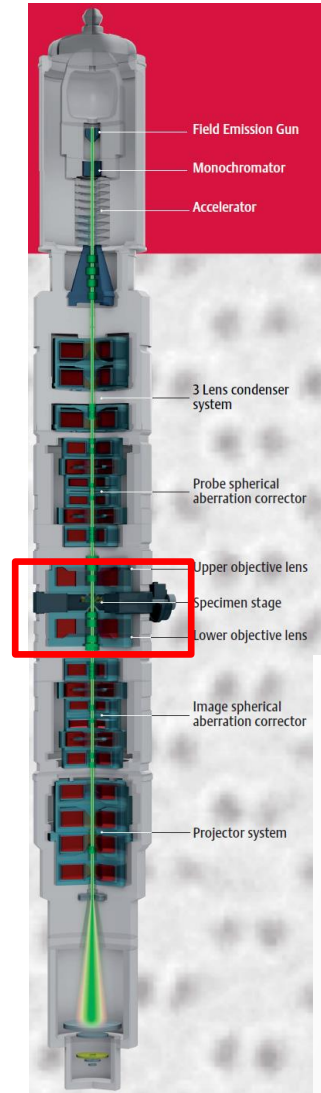
- Introduction
- Sample Preparation
 - Conventional Techniques
 - Focused Ion Beam Techniques
 - Ga ion
 - Plasma
 - Plasma + Laser
- Artifacts caused by bad sample preparations



Helios 5 CX

Sample Position in TEM

Side Entry Holder

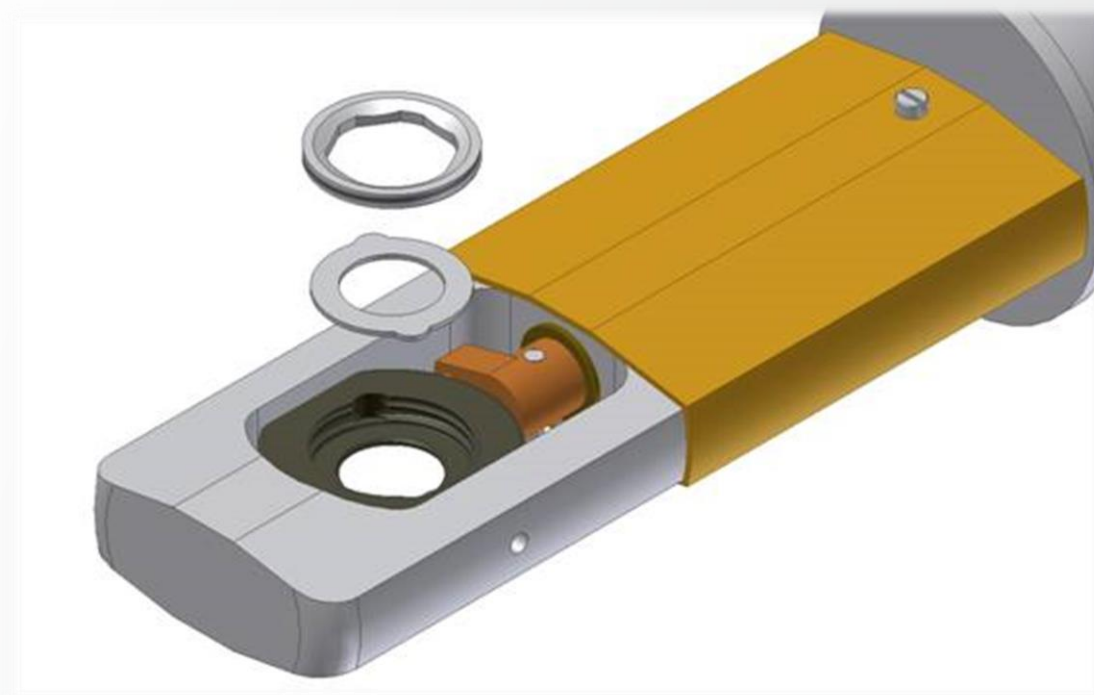
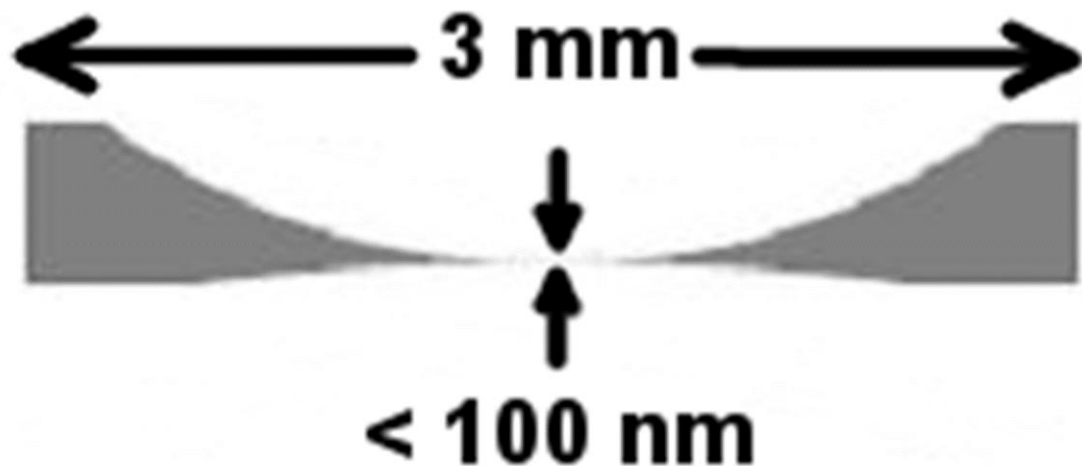


TEM Sample Requirements

Electron Transparent!

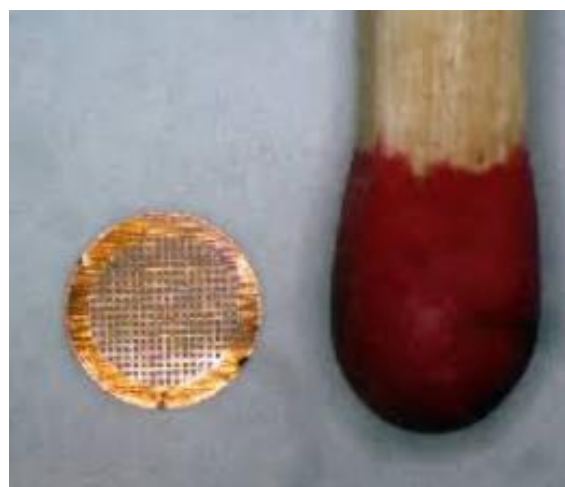
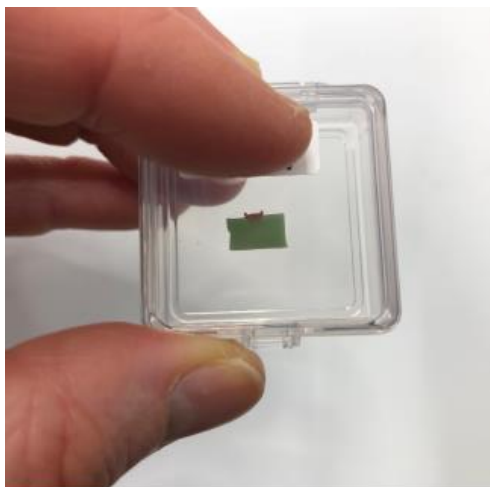
Specimen's requirements:

- Fit into TEM holder cup (3 mm disc)
- Electron transparent (< 100 nm)



TEM Sample

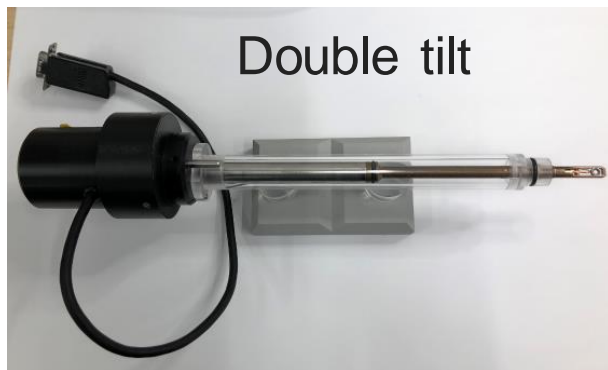
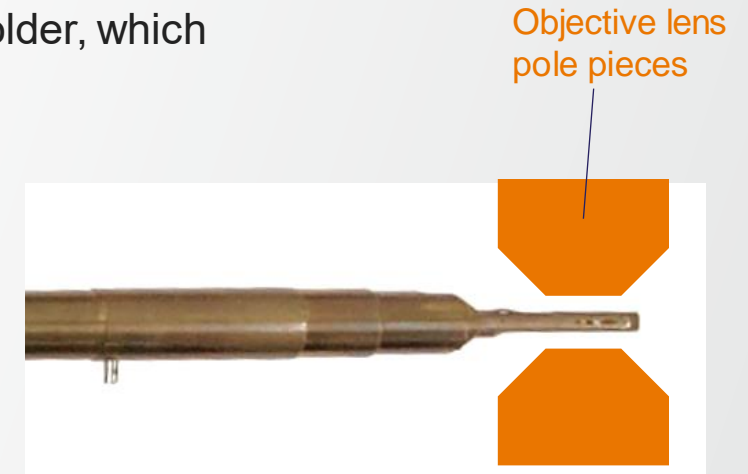
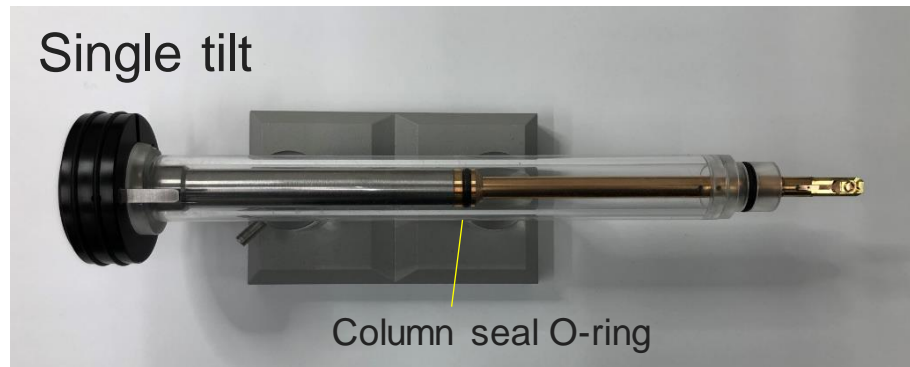
Shape and Size of various TEM Grid



Sample Holders

A Single and Double Tilt TEM Holder

On a Materials Science TEM, the sample is normally inserted into the narrow gap between the objective lens pole pieces (i.e., into the middle of the objective lens) using a “side entry” holder, which looks like this:



Thermo Fisher TEM Holder

TEM Sample Preparation – Non-Biological Sample

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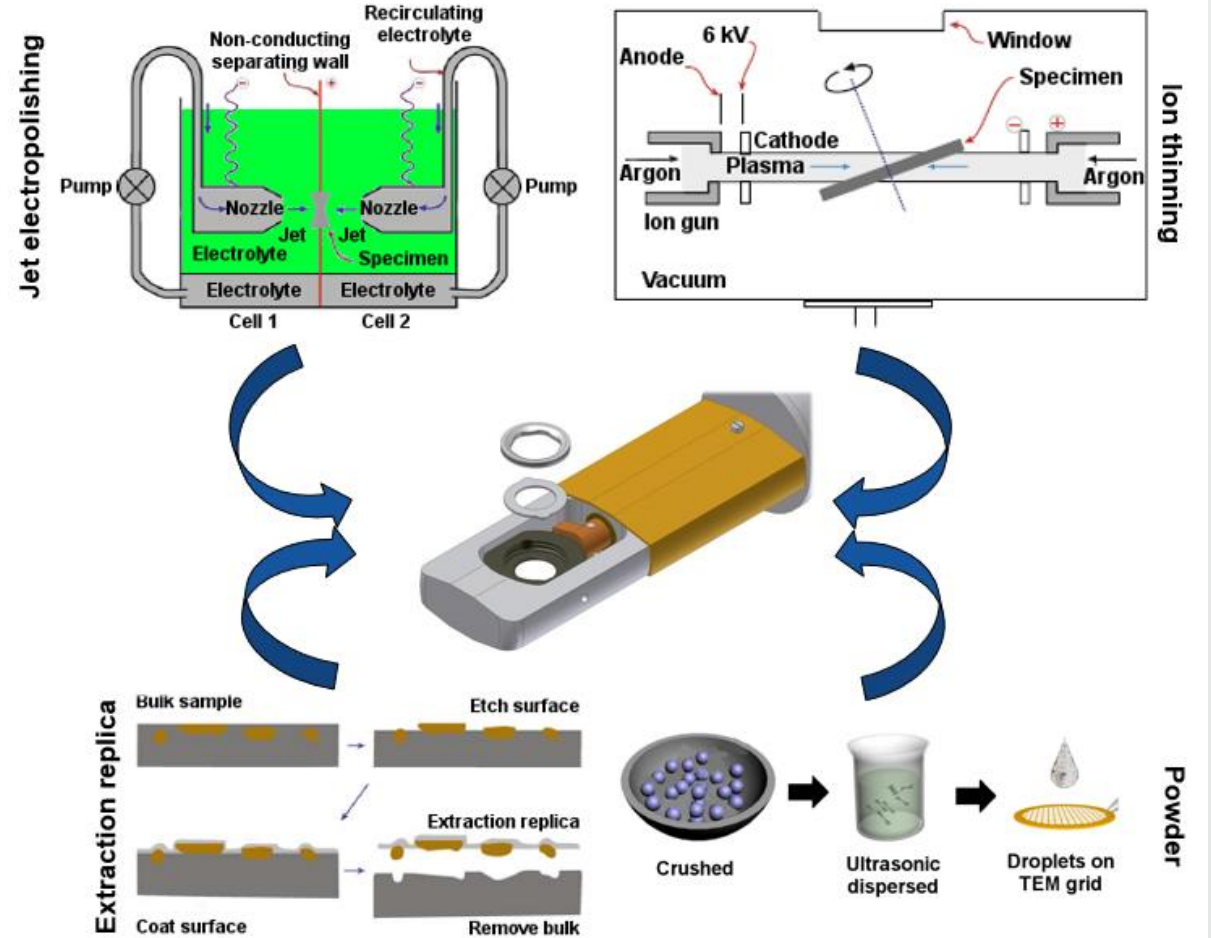
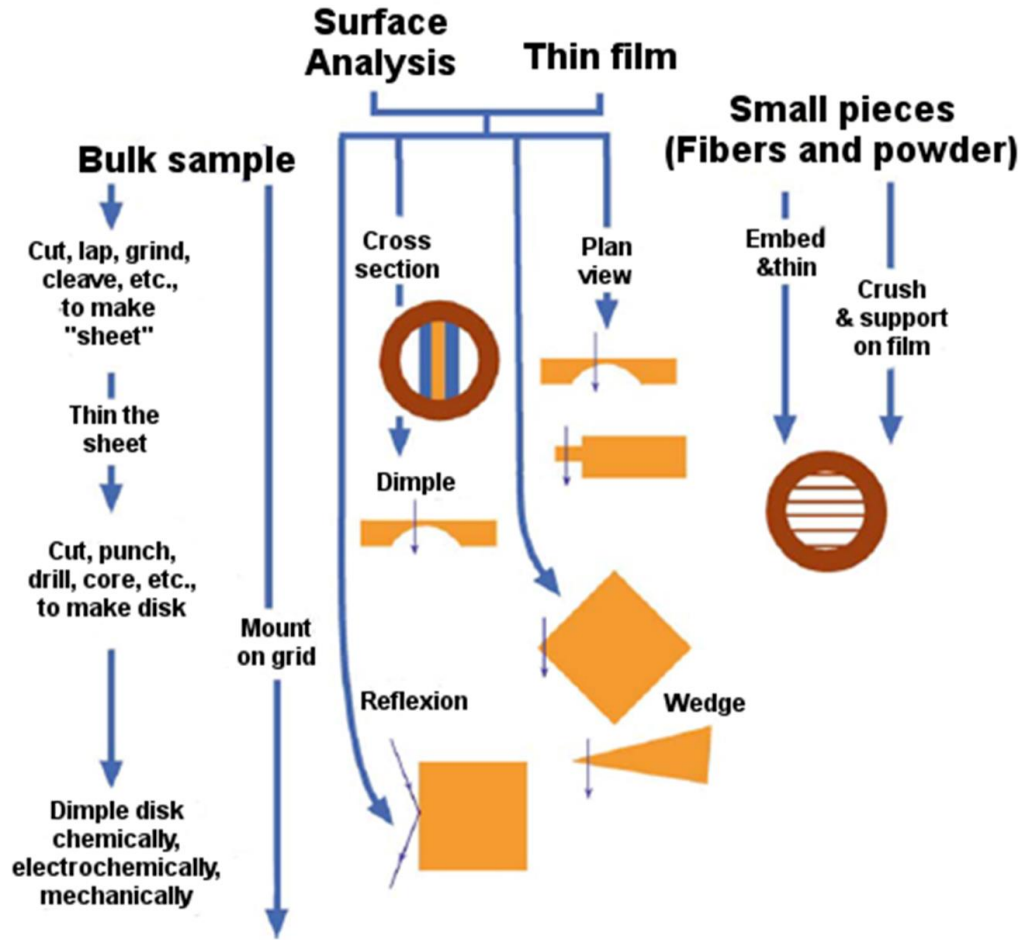
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Scios 2

Non-Biological Sample Preparation

Conventional Techniques



David B. Williams and C. Barry Carter, *Transmission Electron Microscopy, A Textbook for Materials Science*, Springer Science Business Media, LLC 1996, 2009
http://bsa.bionanomaterials.ch/images/step_tem.png
<http://www.jdcsh.com/Upfile/86563302-61e8-477a-a30a-17f614769cd1.jpg>

Non-Biological Sample Preparation

Conventional Technique: Powder Sample Preparation



Movie Courtesy Fangren Shen, Shanghai Nanoport

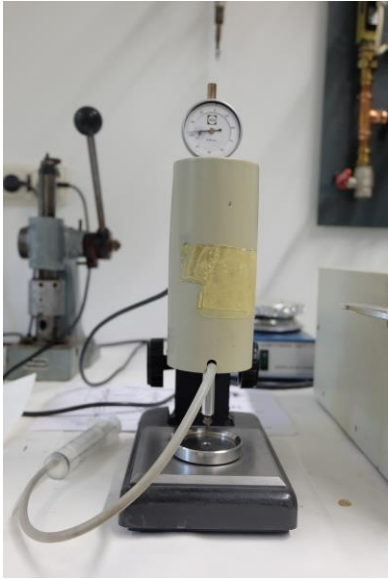
Non-Biological Sample Preparation

Powder Sample Preparation

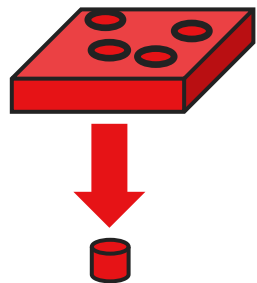
- Procedure:
 - Drop small amount powder into glass tube or microcentrifuge
 - Fill the tube with ethanol or distilled water
 - Sonicate the solution in an ultrasonic bath
 - Using a pipette, drop a small amount of the solution ($\approx 1 \mu\text{l}$) on the TEM grid
 - Heat the grid, so the ethanol or other solution is evaporated
- Tips:
 - Use only a small amount of the sample (a tip on the spatula or 1 mg is already enough)
 - Typically, two minutes of sonification is enough, as ultrasonic might alter the sample properties
 - Be careful with impurity due to other elements from tweezers, filter paper, or even tube (use only new tube)
 - Prepare more than one grid, with a number of droplets variations
 - For samples that are air-sensitive, heat the grid in the vacuum condition

Non-Biological Sample Preparation

Conventional Technique: Ion Milling for Bulk sample



Ultrasonic Cutter



≈ 0.5 hour



Disc Polisher



≈ 1 hour



Dimple Grinder



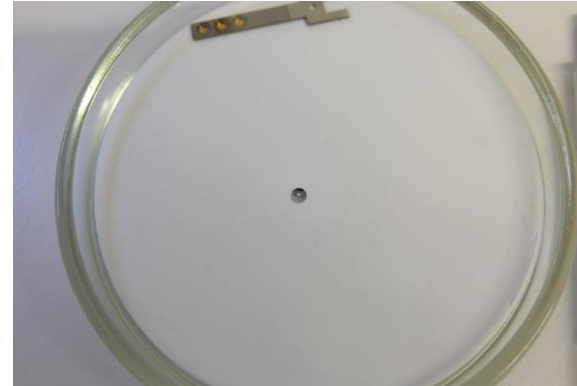
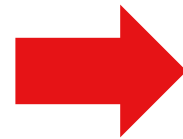
≈ 3 hours

Non-Biological Sample Preparation

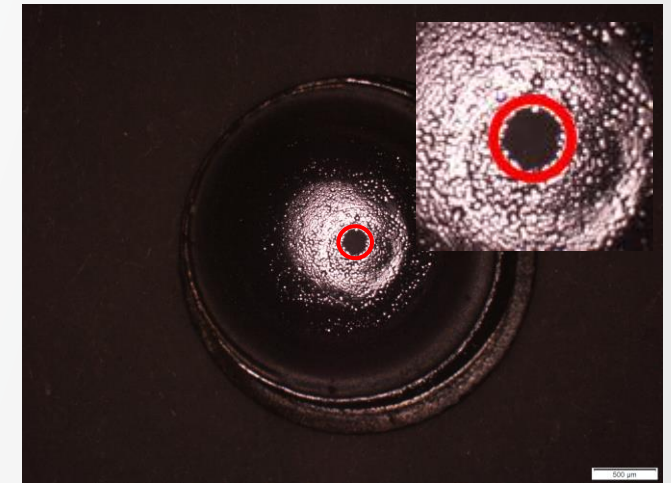
Conventional Technique: Ion Milling for Bulk sample



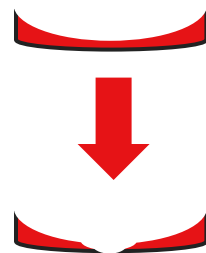
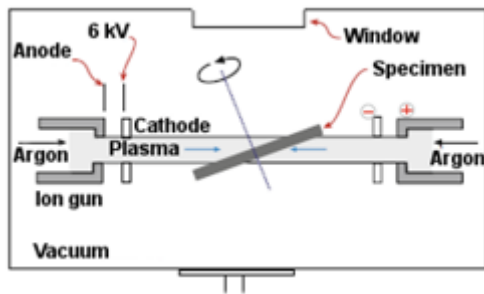
Precision Ion Polishing System



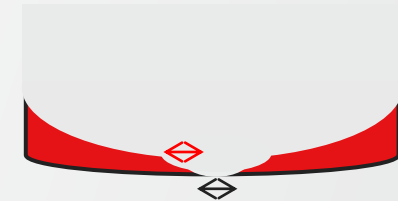
A 3 mm disc with a hole in the center



Investigate area inside the red circle



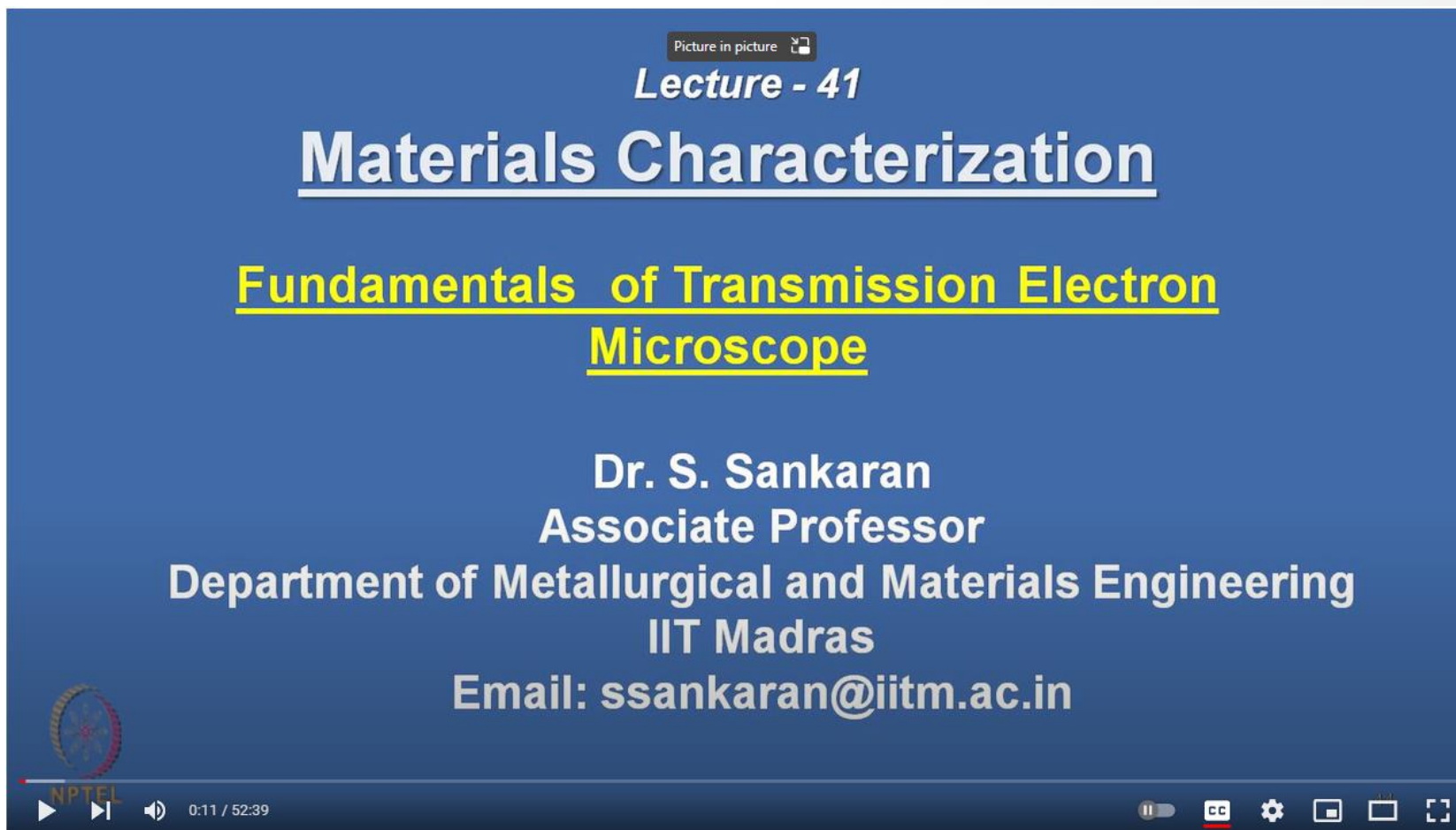
≈ 8 hours - 3 days



≈ 2 – 7 days / sample
Successful rate 30-40%

Non-Biological Sample Preparation

Conventional Technique: Ion Milling for Bulk sample



Picture in picture

Lecture - 41

Materials Characterization

Fundamentals of Transmission Electron Microscope

Dr. S. Sankaran
Associate Professor
Department of Metallurgical and Materials Engineering
IIT Madras
Email: ssankaran@iitm.ac.in

NPTEL

0:11 / 52:39

<https://www.youtube.com/watch?v=1la6bbUtQMs>

<https://www.youtube.com/watch?v=62eT9hr4rUI>

Non-Biological Sample Preparation

Conventional Technique: Ion Milling for Bulk sample

- Procedure:
 - A bulk sample is ground up to 5 mm thickness
 - Cut to 3 mm diameter disc using an ultrasonic cutter
 - Thinning the disc up to 1 mm using a disc polisher
 - Polish both sides to make sure the disc has the same thickness
 - Make the center of the disc further thinner using a dimple grinder
 - Grinding the disc on both sides too.
 - Create an electron transparent area using Precision Ion Polisher System (PIPS)
- Tips:
 - Create significant discs (at least 10 disc/sample) as the success rate is low (more discs are needed for inexperienced users)
 - Use appropriate mixture for epoxy glue (1:10 for resin and hardener)
 - Critical steps:
 - Sample dropped off during disc polishing
 - Make sure the sample is glued perfectly
 - Sample breaks during dimple grinder
 - Pay attention to the initial sample thickness
 - Be careful when switching the sample side
 - Be cautious of material redeposition during PIPS
 - Ion beam angles depend on materials and initial thickness
 - Initial polishing step 8-10° and down to 3° for final thinning
 - Check the surface condition and stop the polishing when the redeposition appears

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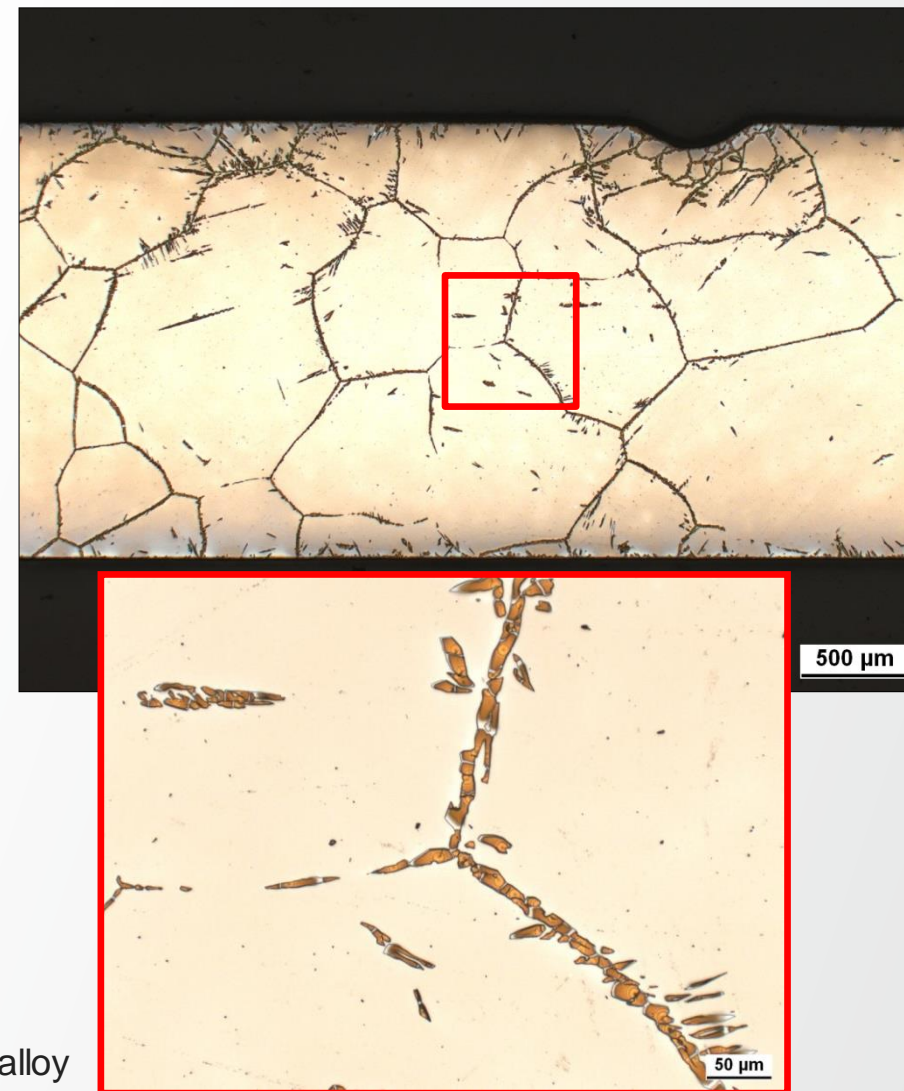


Helios G4 PFIB UXe

Non-Biological Sample Preparation

Focused Ion Beam Technique

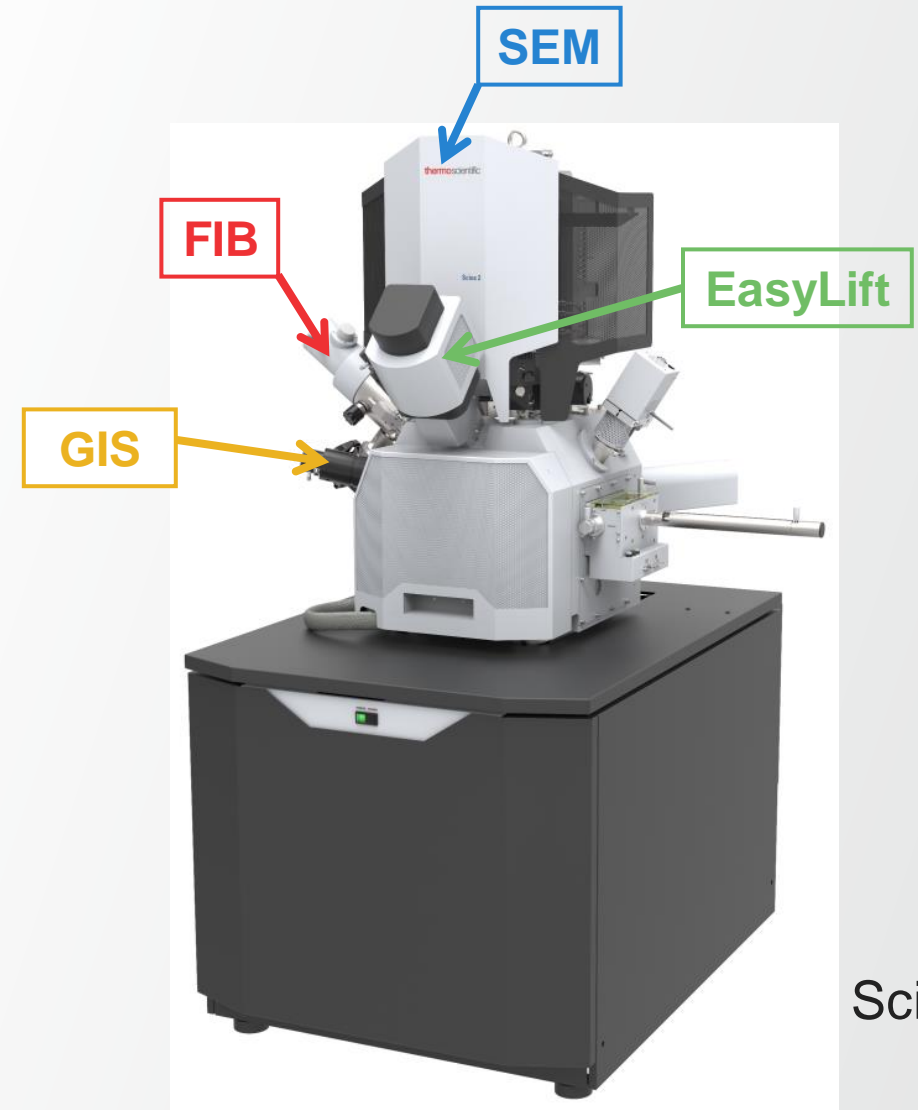
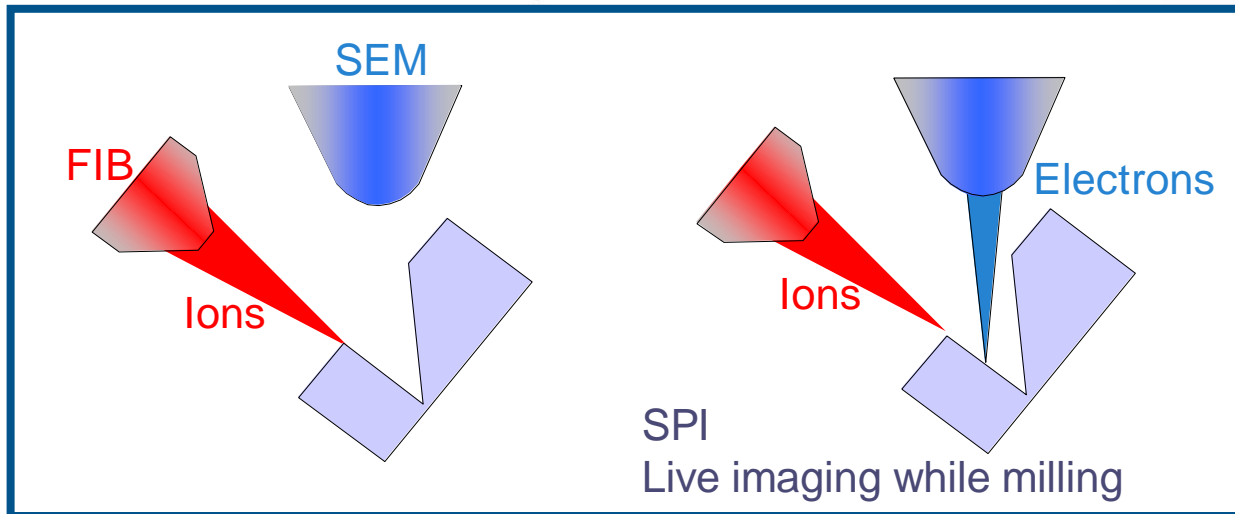
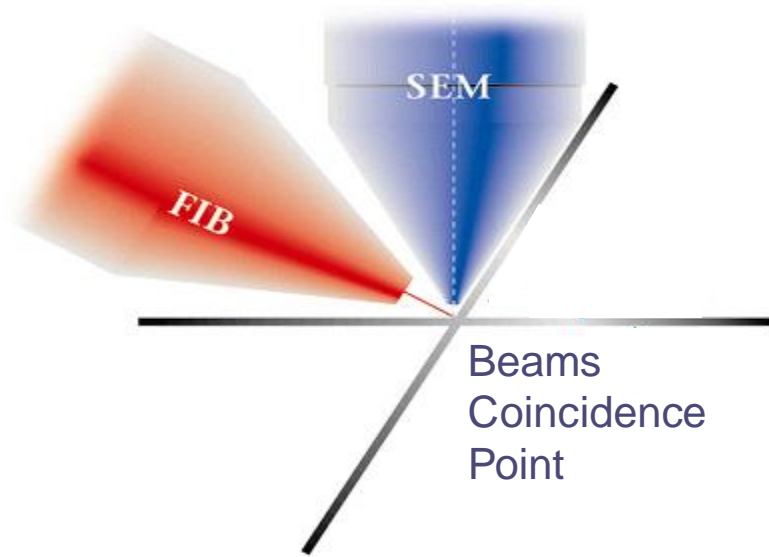
- Target grain boundaries and end-point on features with nanometer precision
- Examine Interfaces between hard and soft materials
- Target specific orientations in crystalline materials
- Prepare multiple samples and keep bulk samples intact for repeat analysis



Sigma phase formation and Fe-Cr based alloy

Focused Ion Beam Technique

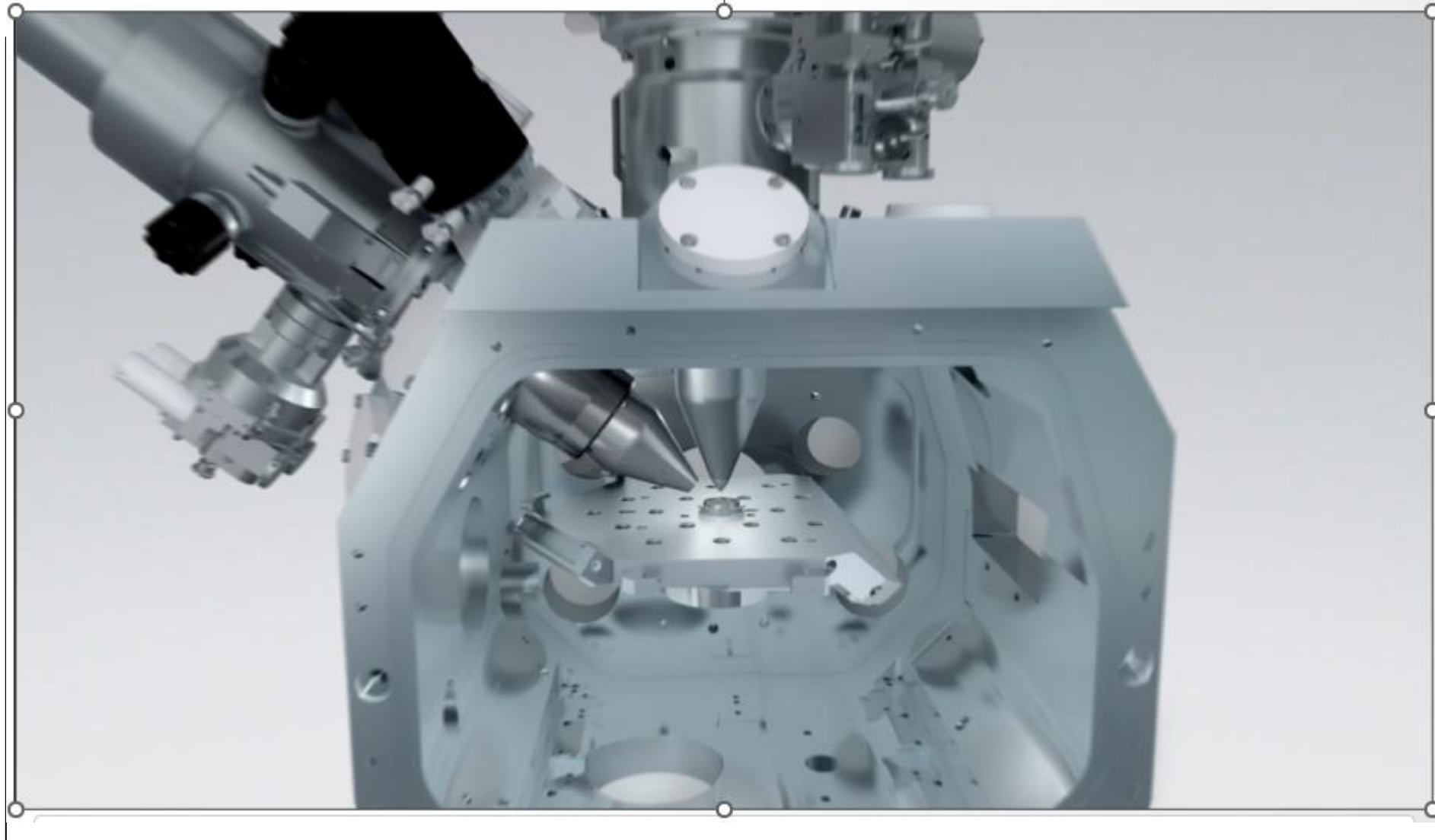
Principle of a DualBeam™



Scios 2

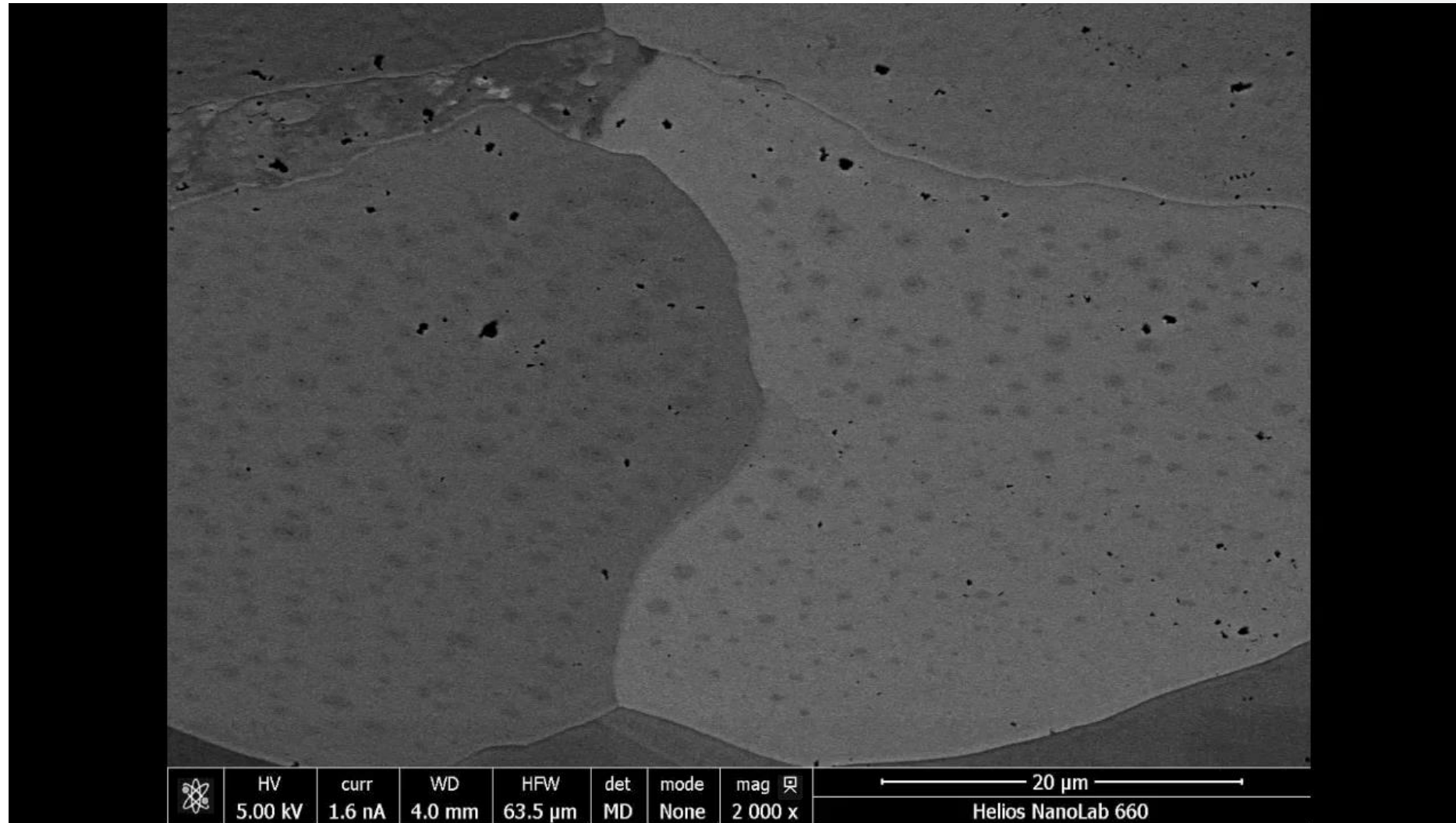
Focused Ion Beam Technique

How does Dual Beam FIB Work?



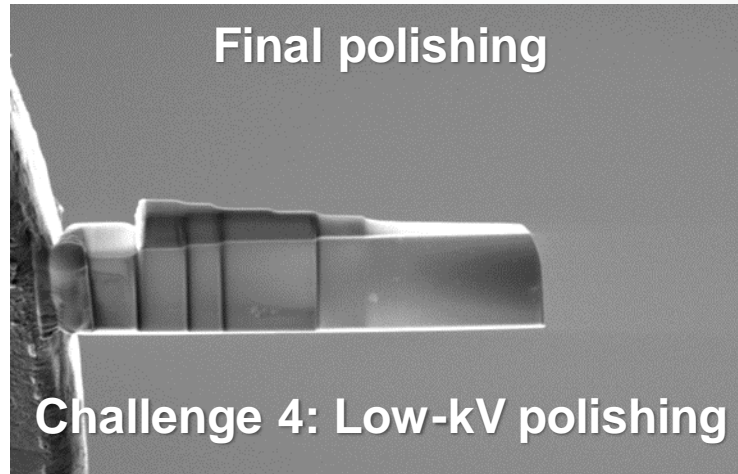
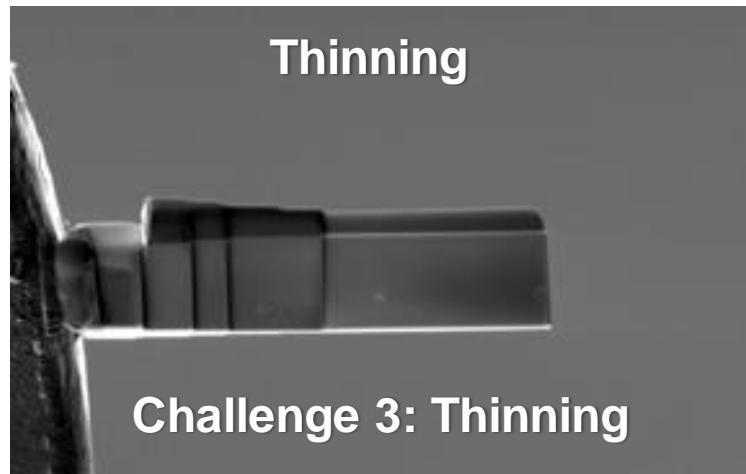
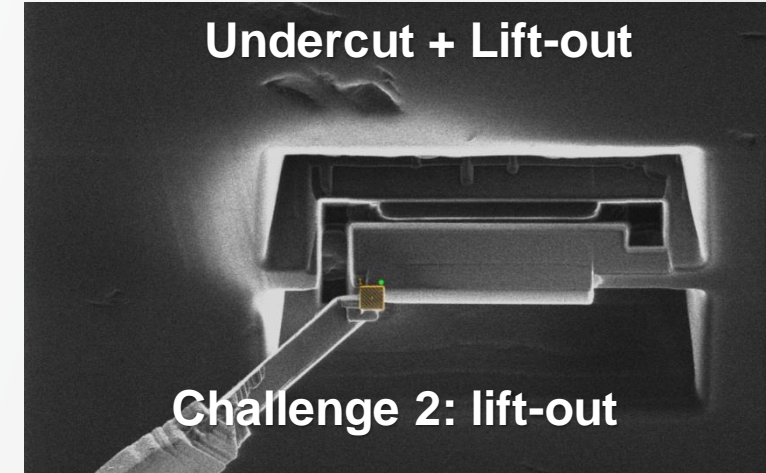
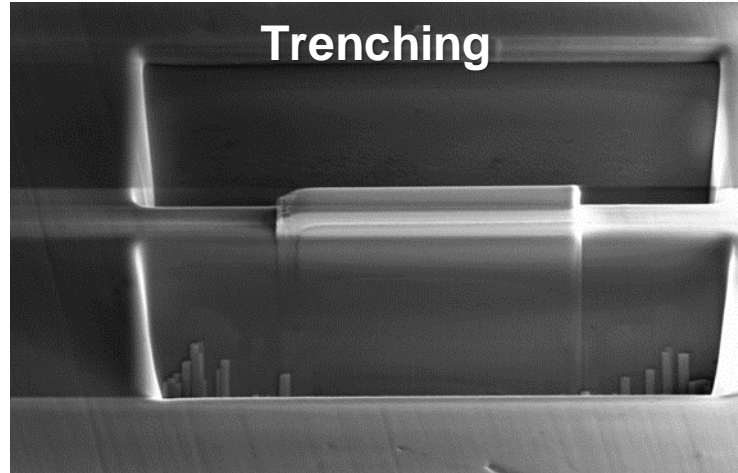
Focused Ion Beam Technique

S/TEM Sample preparation workflow



Focused Ion Beam Technique

S/TEM Sample preparation workflow – Challenges

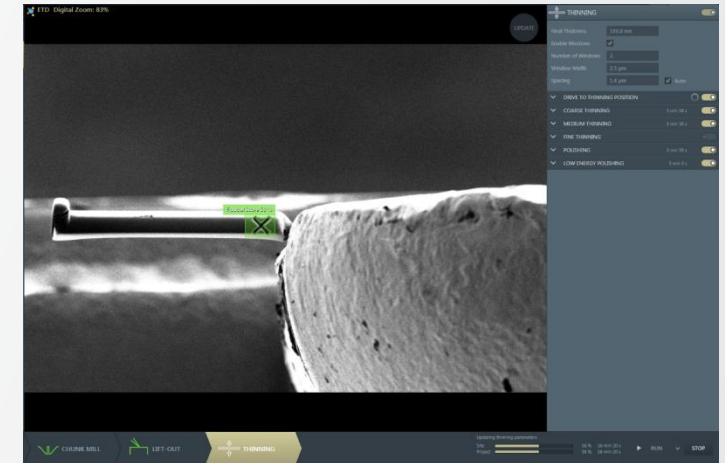
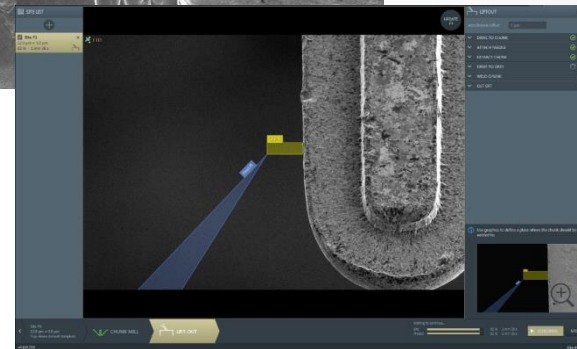
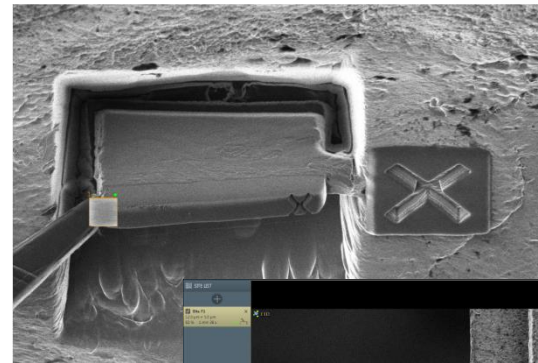
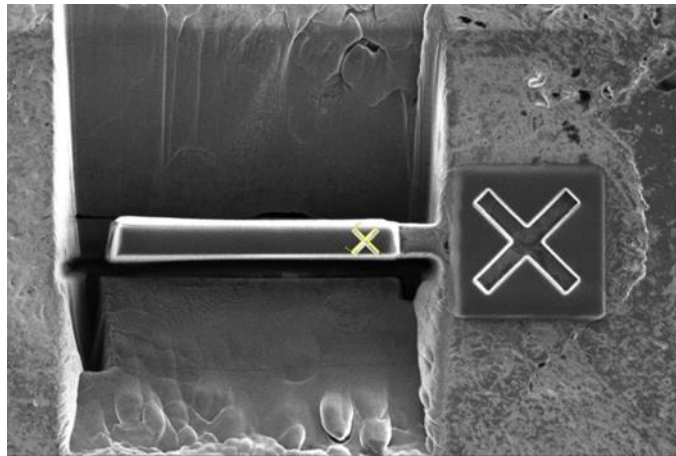
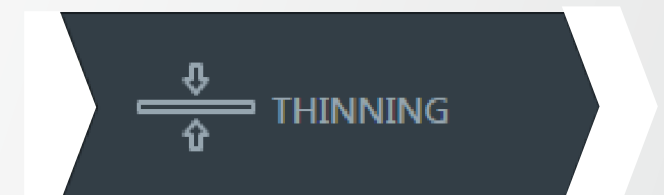
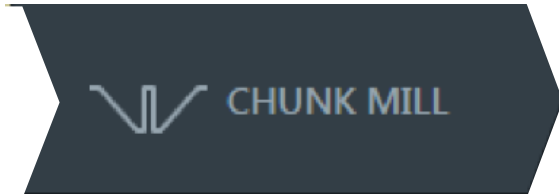


1. E-beam deposition
2. Lift-out
3. Final thinning
4. Low-kV polishing
5. Expert level operator is needed

AutoTEM 5 offers complete, fully automated in-situ lift-out preparation process

Focused Ion Beam Technique

AutoTEM 4 – Complete *in situ* Lift-out Workflow



- Automatic
- Automatic with manual recovery
- Guided

- Guided

- Automatic
- Automatic with manual recovery
- Guided

Focused Ion Beam Technique

AutoTEM 4 – Run in 3 clicks

Select template

Define position in the bulk

Define grid position

RUN

The screenshot displays the AutoTEM 4 software interface. At the top, the menu bar includes 'FEI', 'File', 'Project', 'Site', and 'Help'. The main window is titled 'AutoTEM 4' and features a 'SITE LIST' on the left with a '+' icon. The selected site is 'Site #1' with parameters: 12.0 μm x 5.0 μm, 0%, and 37 min 34 s. The interface is divided into three columns: 'In-situ lift-out', 'Ex-situ lift-out', and 'Cross section'. Each column has a 'Top-down default template' and a 'Top-down Al' option. The 'In-situ lift-out' column has a green checkmark. Below these columns are two large panels: 'Chunk Position' and 'TEM Grid Position', each with an 'UPDATE' button. The 'Chunk Position' panel lists preconditions: Stage at eucentric distance and Z linked, Tilted to 52°, and Ion beam focused on the sample. The 'TEM Grid Position' panel lists preconditions: Stage at eucentric distance and Z linked, Ion beam focused on the grid, and HFW around 400 μm. At the bottom, a workflow bar shows 'CHUNK MILL', 'LIFT-OUT', and 'THINNING' steps. The status bar at the bottom right shows 'Site: N/A', 'Project: 0%', and '37 min 34 s', with 'RUN' and 'STOP' buttons. The version number 'v4.0.0.375' is visible in the bottom left corner.

Focused Ion Beam Technique

AutoTEM 4 – Chunk mill

Chunk mill

CREATE FIDUCIAL

GROUND

PROTECTIVE LAYER

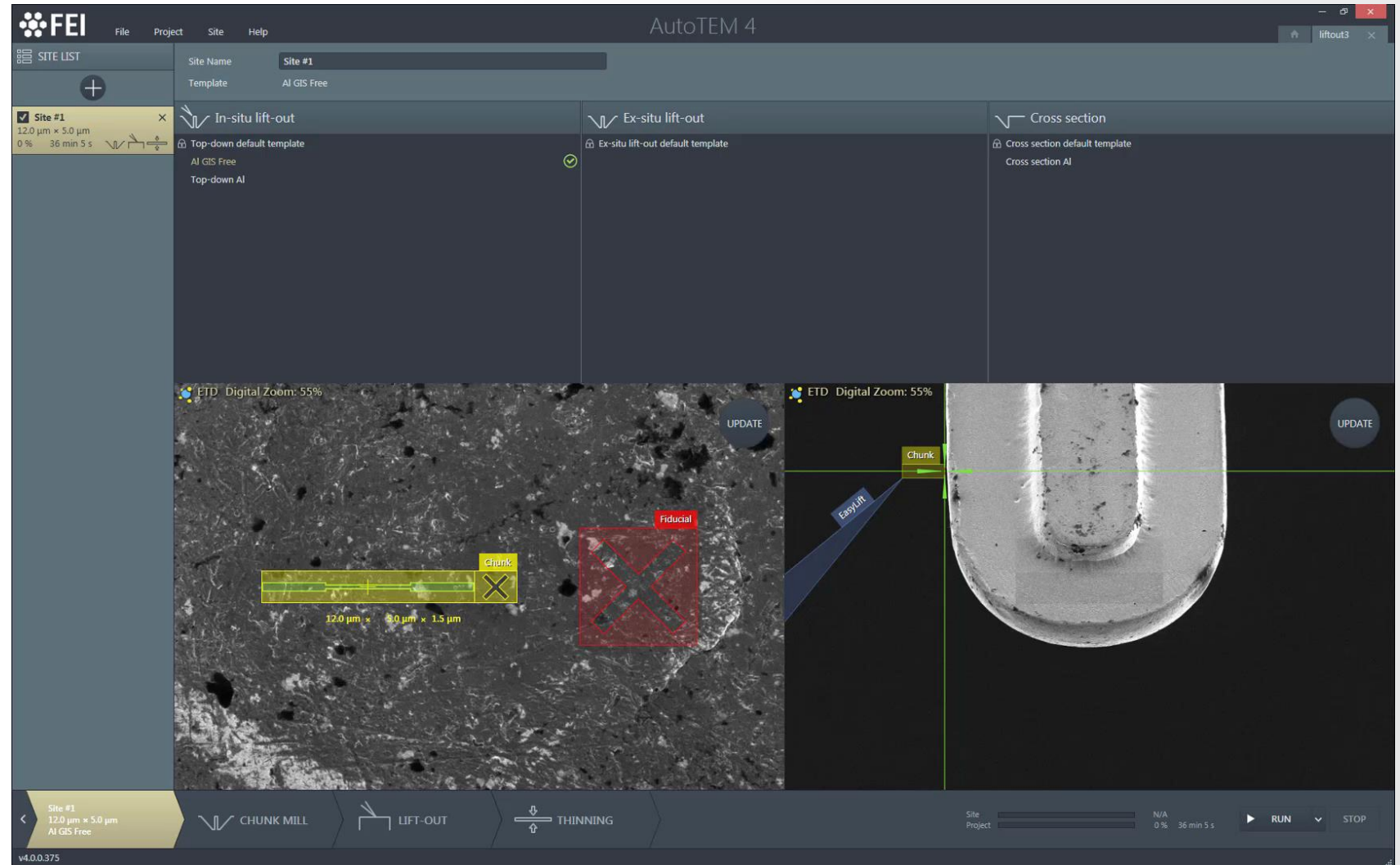
ROUGH MILLING

MEDIUM MILLING

CUTOUT

CLEANUP

CREATE THINNING FIDUCIAL



Focused Ion Beam Technique

AutoTEM 4 – Guided in-situ lift-out

Guided lift-out

DRIVE TO CHUNK

ATTACH NEEDLE

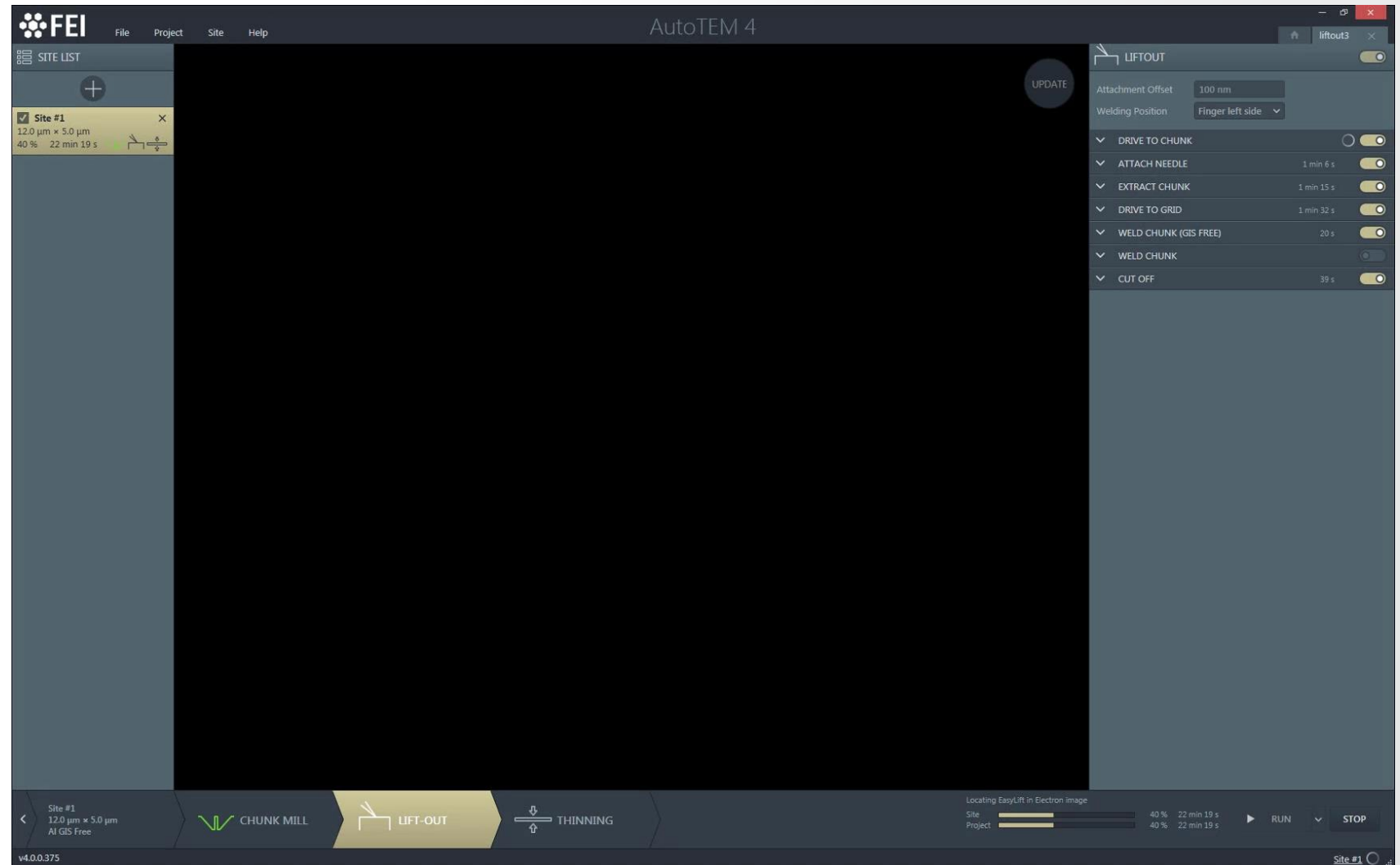
EXTRACT CHUNK

DRIVE TO GRID

WELD CHUNK

WELD CHUNK (GIS FREE)

CUT OFF

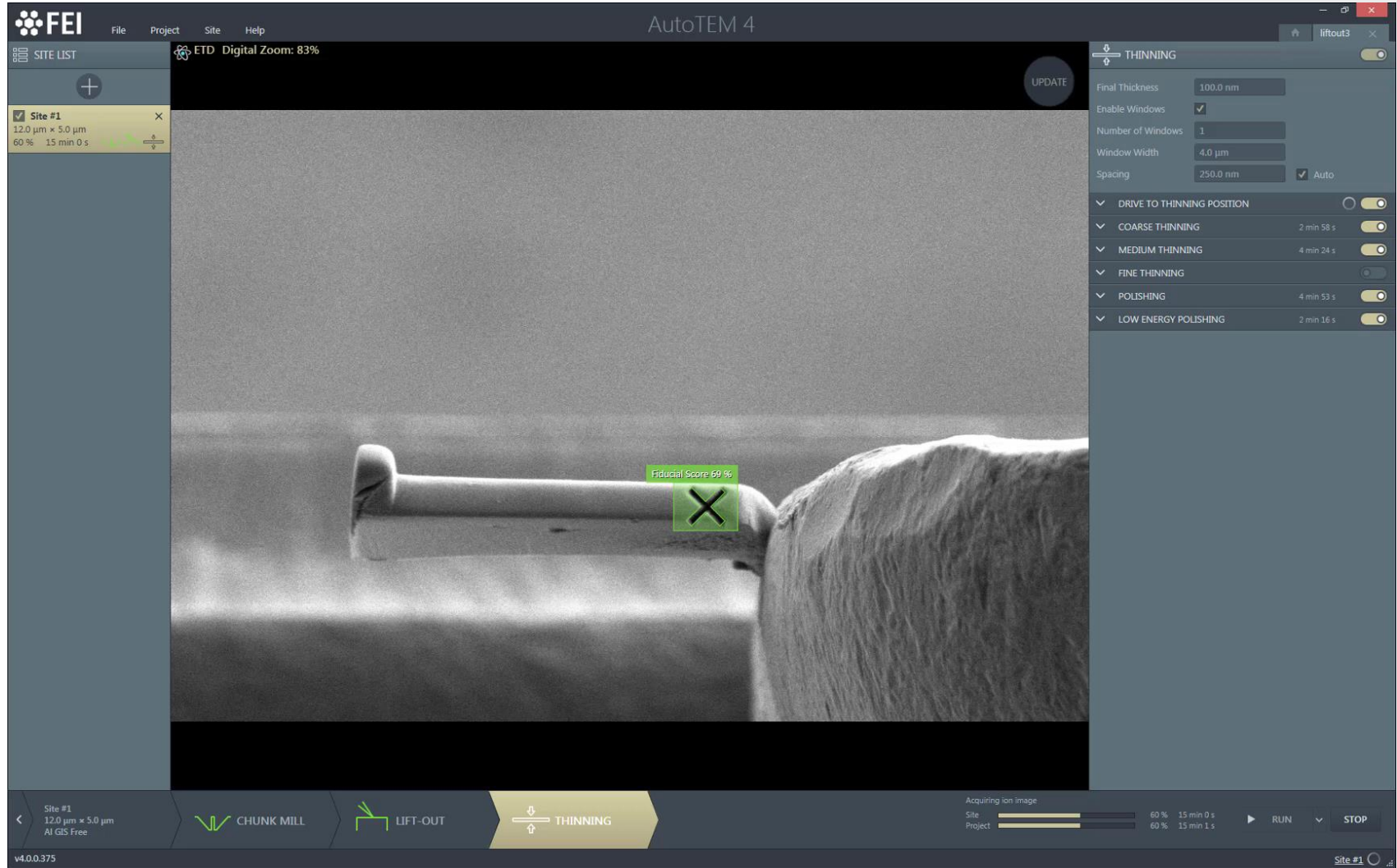


Focused Ion Beam Technique

AutoTEM 4 – Thinning

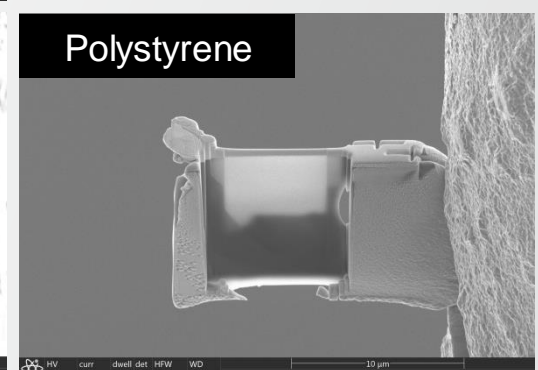
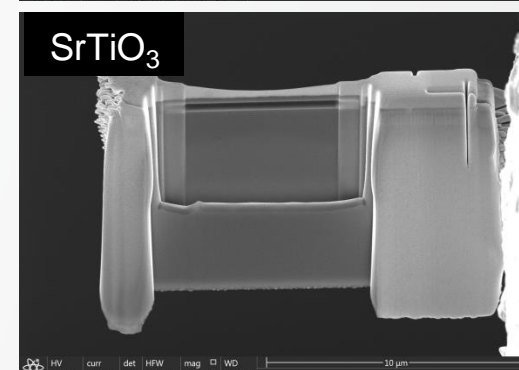
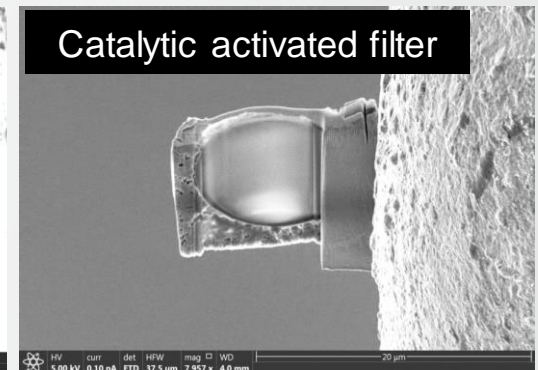
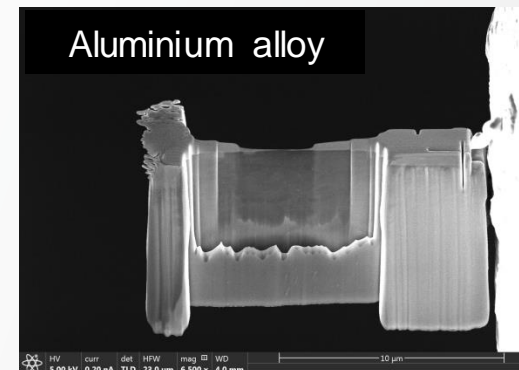
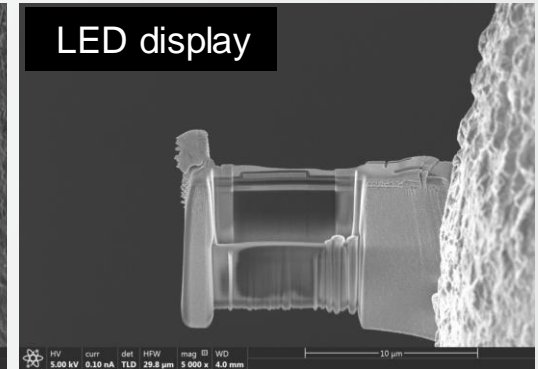
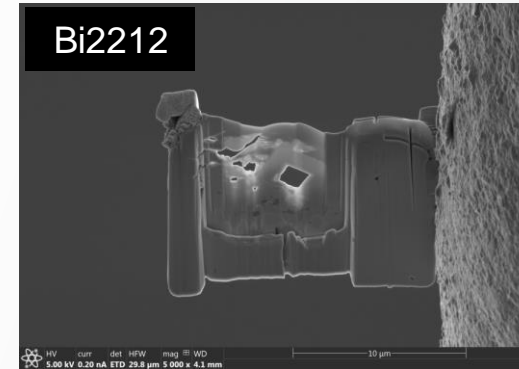
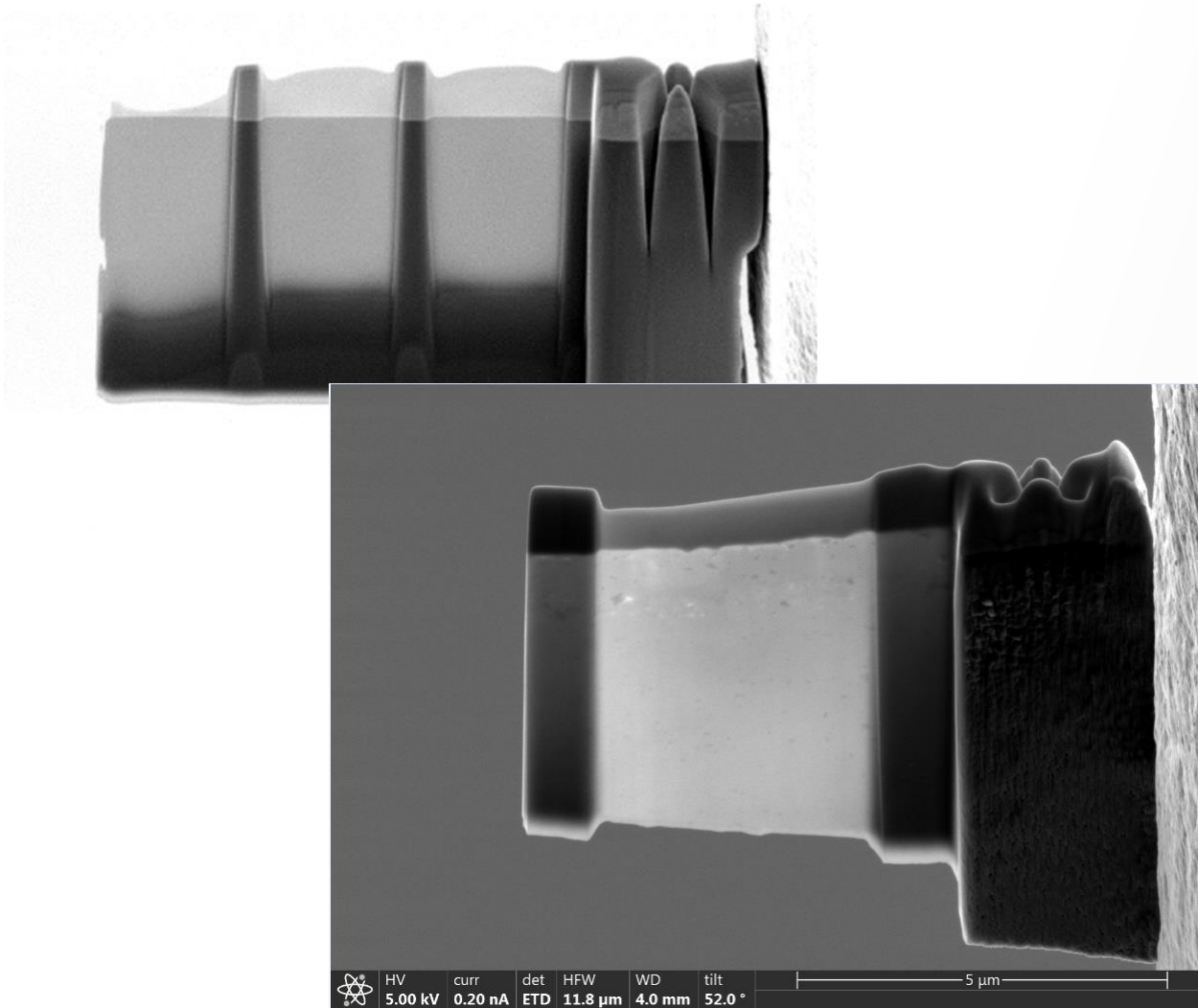
Thinning

- DRIVE TO THINNING POSITION
- COARSE THINNING
- MEDIUM THINNING
- FINE THINNING
- POLISHING
- LOW ENERGY POLISHING



Focused Ion Beam Technique

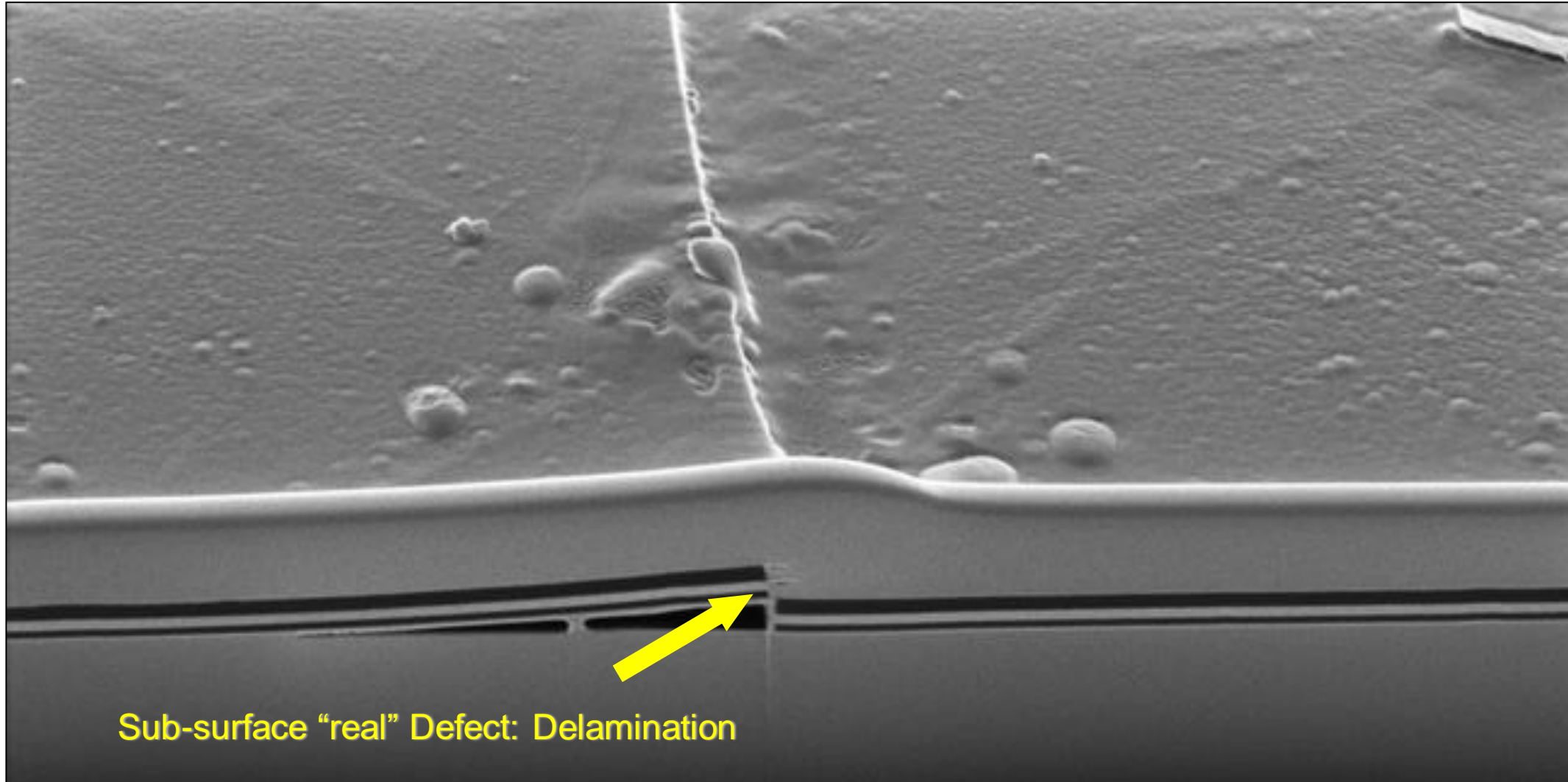
Robust, predictable results for a wide range of materials



Courtesy: Remco Geurts, Thermo Fisher

Focused Ion Beam Technique

3D characterization by FIB

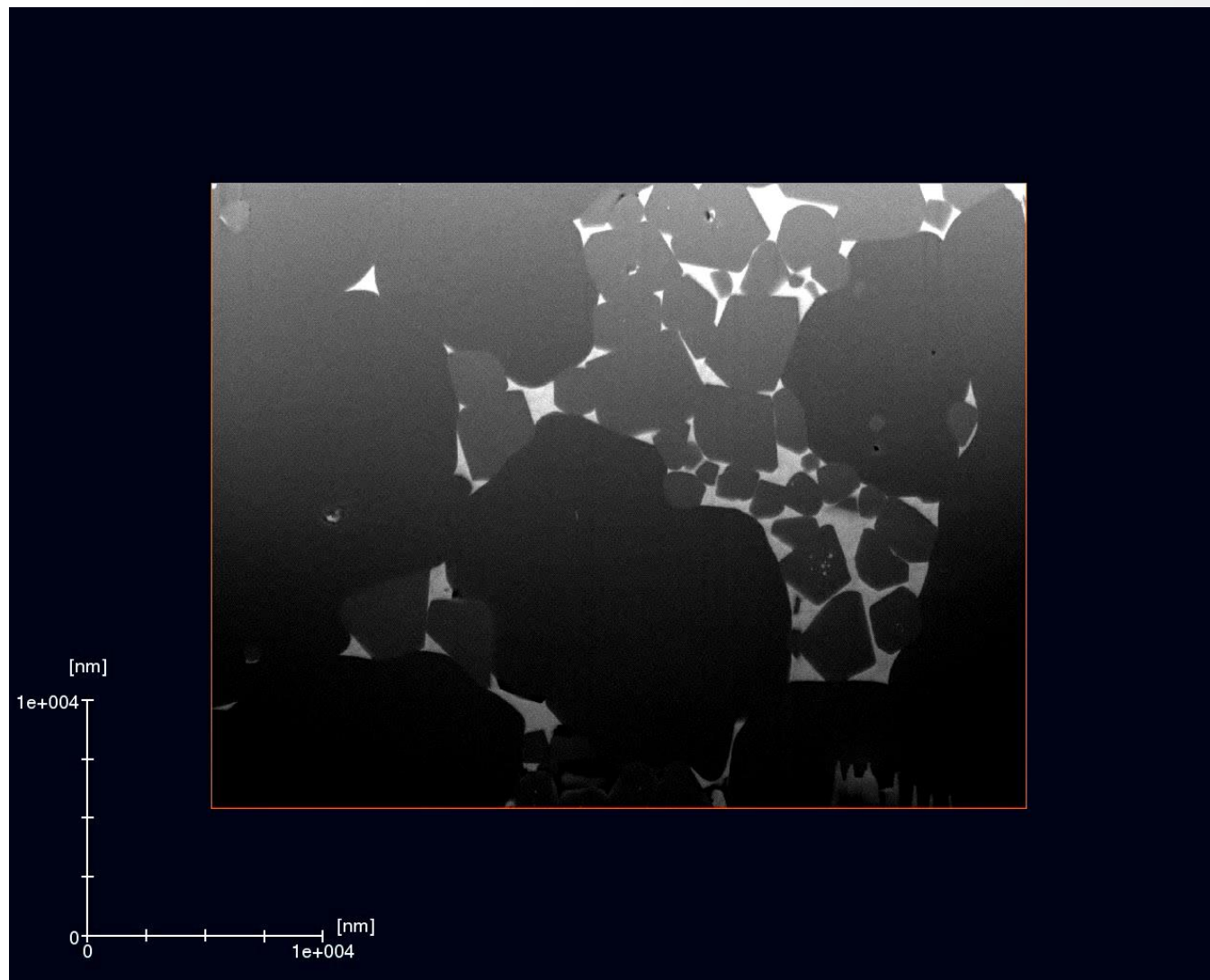
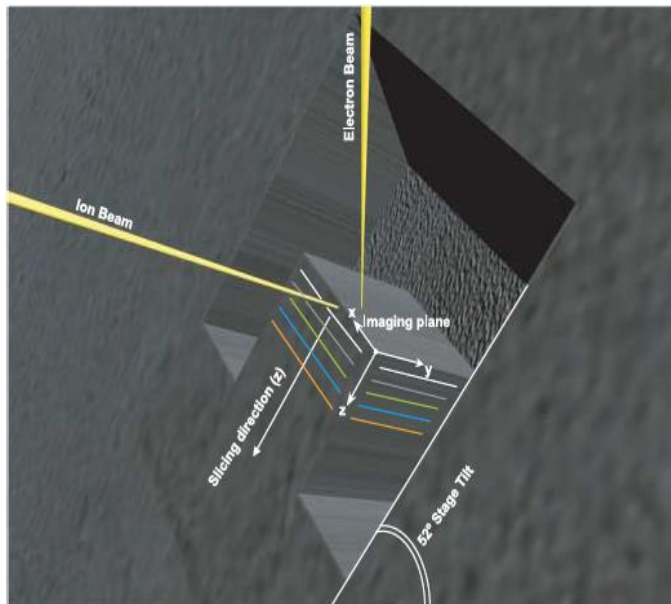


Sub-surface defect, anti-reflective coating on clear plastic motorcycle visor

Sub-surface "real" Defect: Delamination

Focused Ion Beam Technique

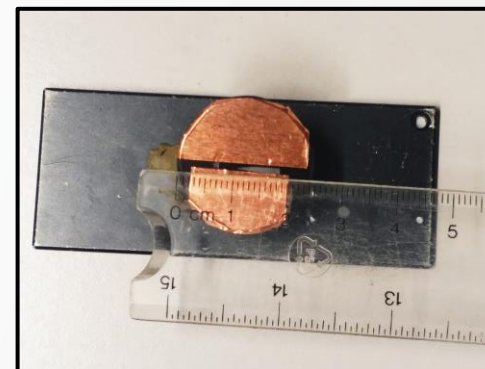
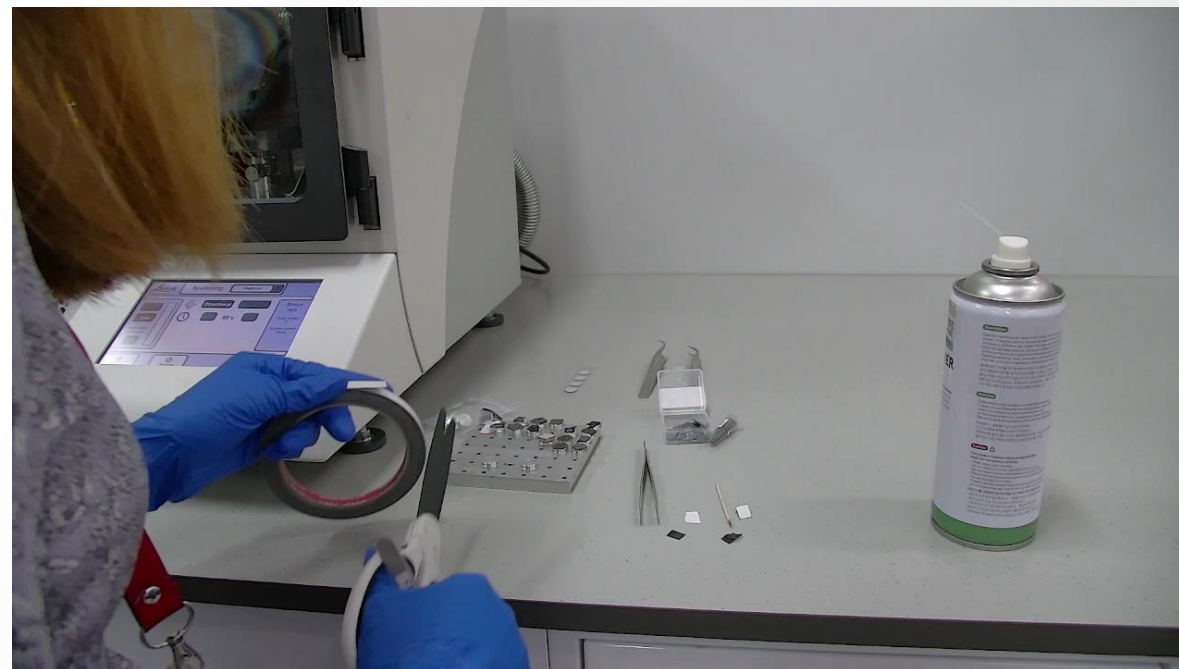
3D characterization by FIB



Focused Ion Beam Technique

Sample pre-conditioning before FIB preparation

- Pre-coated with gold, carbon, or Pt
 - Powder and surface-sensitive samples
 - Ga-ion is very destructive. It can remove 10-20 nm surface material in a single scan
 - Increase sample conductivity
 - As a reference for the final sample condition, i.e., the selected layer is destroyed by the Ga-ion
- Non-conductive sample
 - Can reduce image quality and introduce sample drift.
 - If coating strategy can't be performed, use a silver paste to glue the sample into the FIB sample holder and cover some parts of the sample with it.
 - Use copper tape to cover most of the sample to reduce the charging effect.



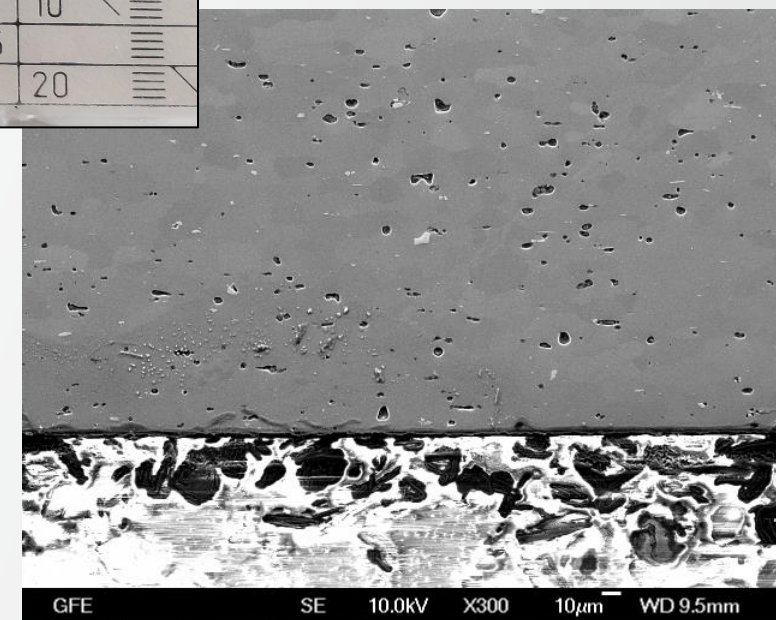
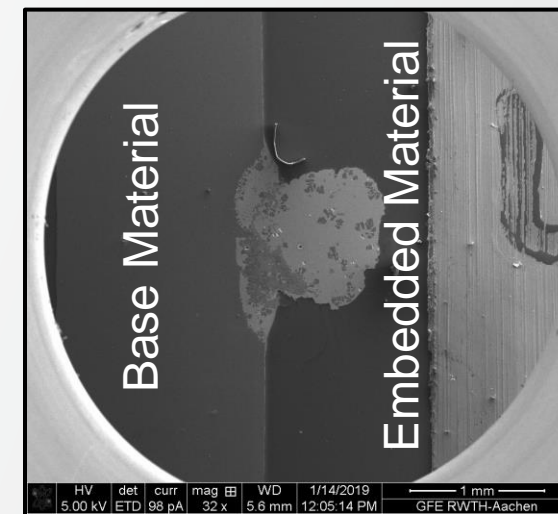
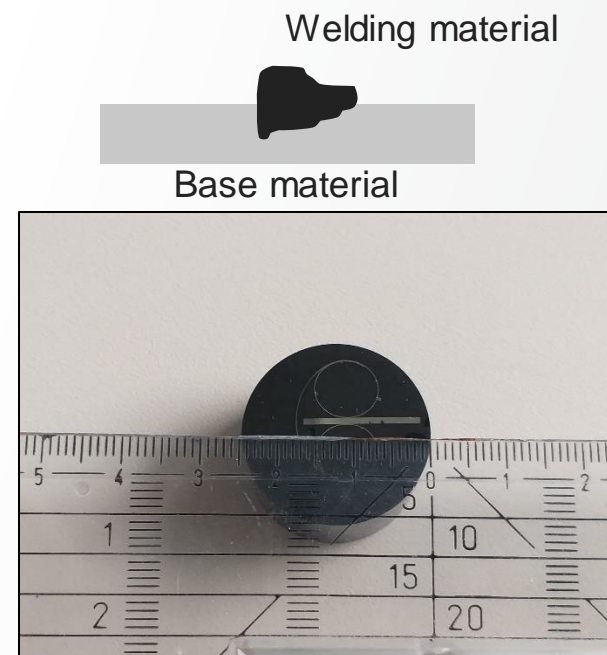
Movie Courtesy Wang Yi, Shanghai Nanoport

Photograph Fadli Rohman Research Center for Physics LIPI (BRIN) and GFE RWTH Aachen

Focused Ion Beam Technique

Sample pre-conditioning before FIB preparation

- Embedded samples
 - A very thick cross-section samples: soldering materials, oxide layer containing samples, or sample with precipitates distributions.
 - Larger investigation area
 - Eliminated FIB depth milling condition ($4\ \mu\text{m}$)
- Type of embedded materials:
 - Epoxy if the area of interest is not located at the sample surface. The charging effect as epoxy is non-conductive.
 - Cu-C mixed based embedded
 - It doesn't introduce a charging effect
 - Be careful with redeposition of Cu-C particles during surface polishing



Non-Biological Sample Preparation

Focused Ion Beam Technique

- Preparation prior FIB
 - Coated the sample surface with carbon, gold, or platinum
 - For a specific area, investigate the sample using EDS or EBSD
 - Make sure the sample's dimensions is allowed by the FIB chamber
 - Make sure the sample is clean, so it won't affect the vacuum condition
 - Non-bulk samples can be prepared as embedded samples before being prepared by FIB
- Tips:
 - FIB is a local and specific preparation technique
 - Make sure to know what and where the lamella need to be prepared
 - A prior investigation is necessary
 - Choose the protection layer wisely
 - EDS overlapped signals with elements containing sample
 - Contrast differences, i.e., W/Pt can not be used for a sample containing a lower atomic number
 - Beware of artifacts due to:
 - Choose of tilt angle
 - HT for cleaning step
 - It all depends on the sample's materials
 - Small precipitates due to Ga ion redeposition

TEM Sample Preparation – Non-Biological Sample

Outline

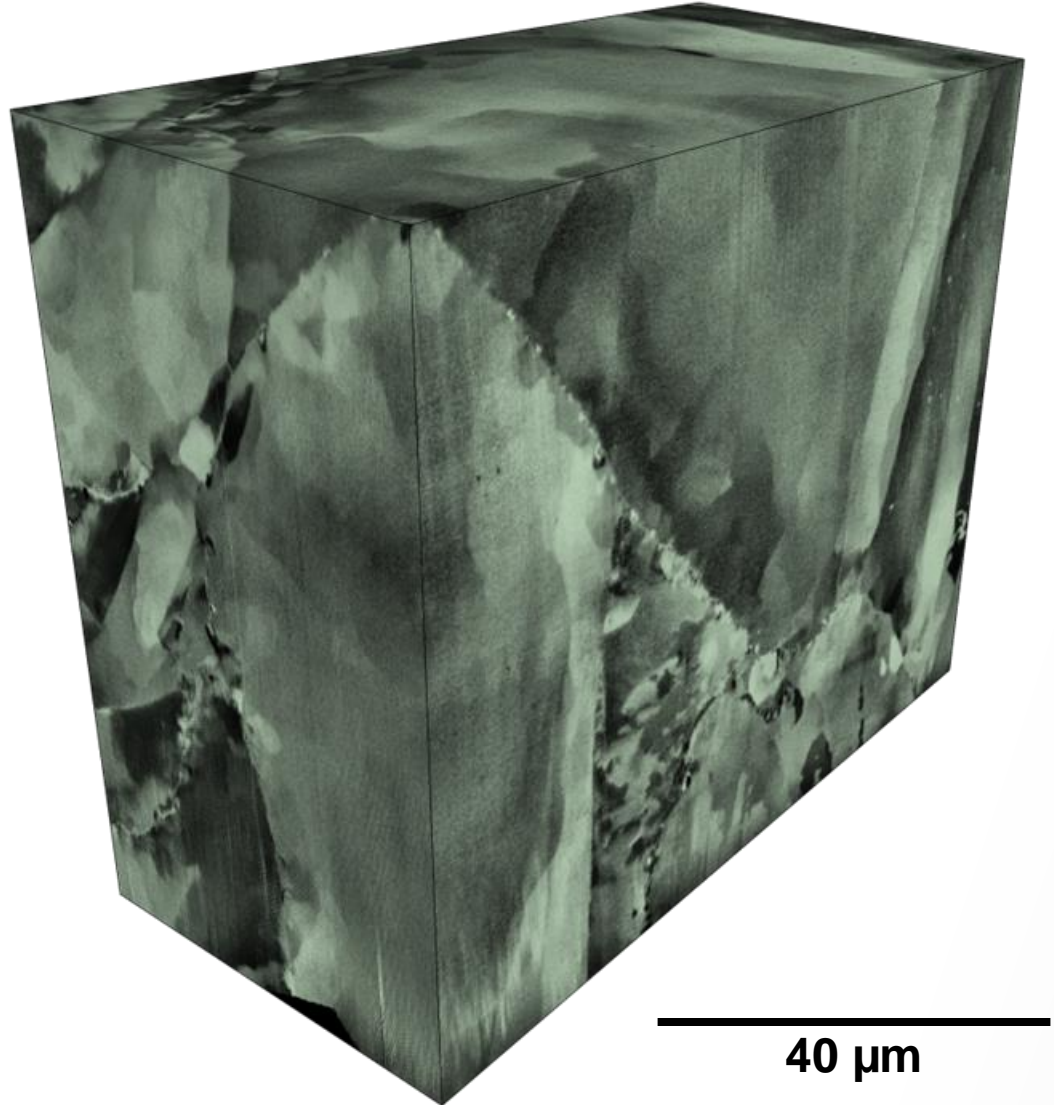
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Helios G4 PFIB UXe

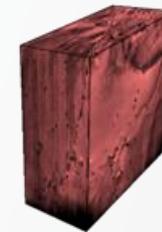
Plasma Focus Ion Beam (FIB)

Helios G4 PFIB – 100x more characterization without compromise

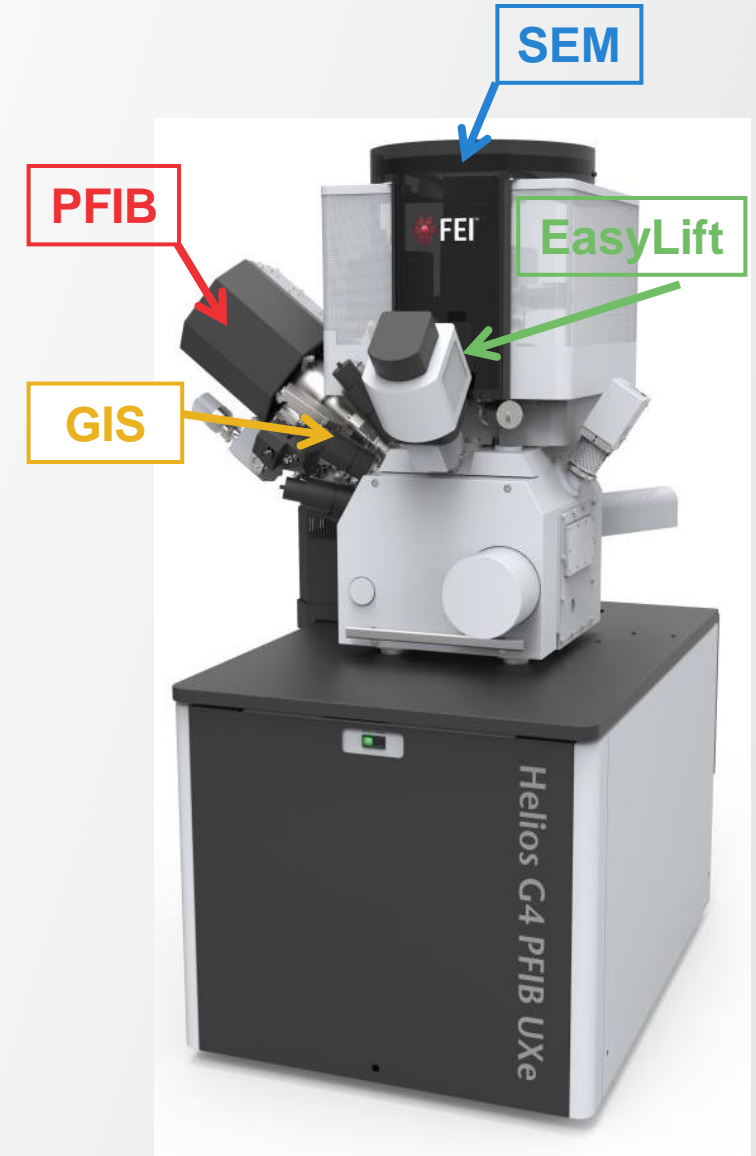


Xe⁺ PFIB

Ga⁺ FIB



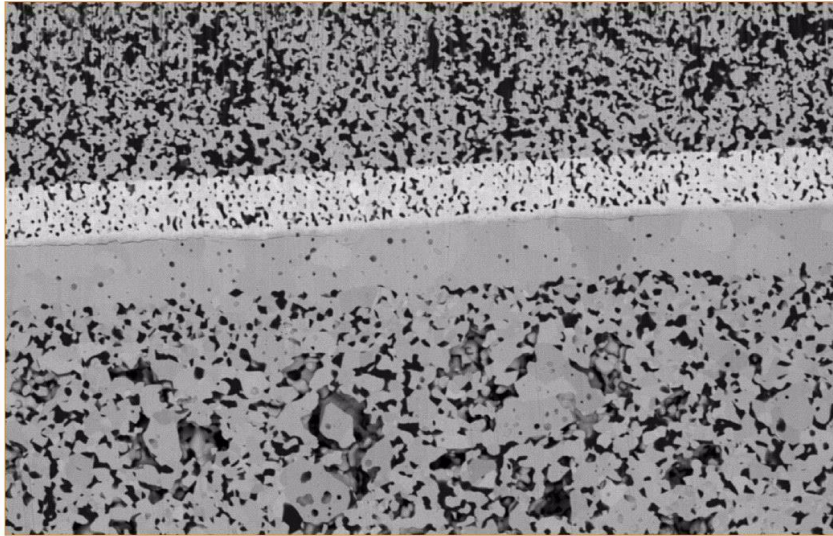
40 µm



Plasma Focus Ion Beam (FIB)

Helios G4 PFIB – High throughput large volume 3D characterization

Solid Oxide Fuel Cell: 3D rendering from anode to the cathode



50 μm

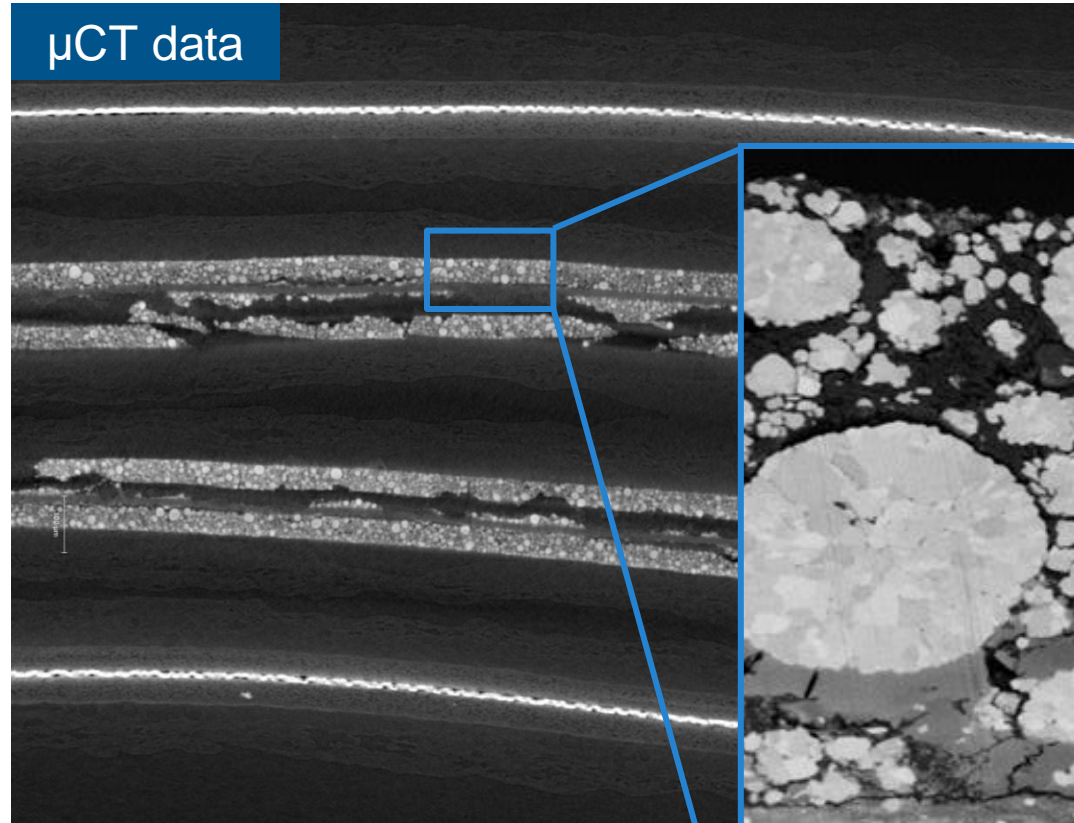
- Reconstruction of the entire fuel cell structure
- The pore space is segmented and a pore network is build
- Balls and sticks represent here pores and pore throats respectively

Sample courtesy: Jochen Joos, KIT

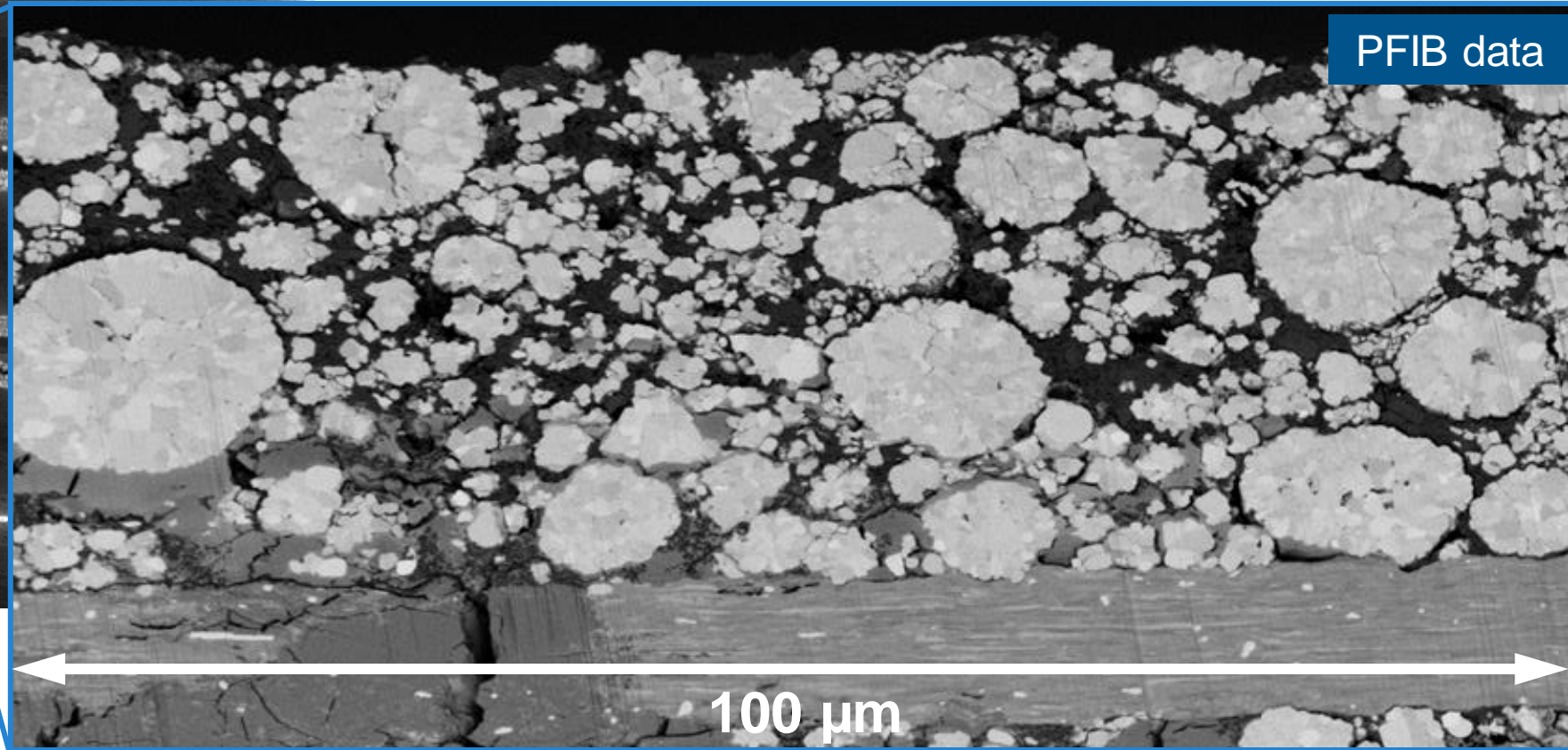
Data acquired: Remco Geurts, Thermo Fisher

Plasma Focus Ion Beam (FIB)

Helios G4 PFIB – Correlative workflow (μ CT-Dual Beam)



Imaging of **relevant volumes** in Li-Ion battery electrodes with HeliScan μ CT and Helios PFIB



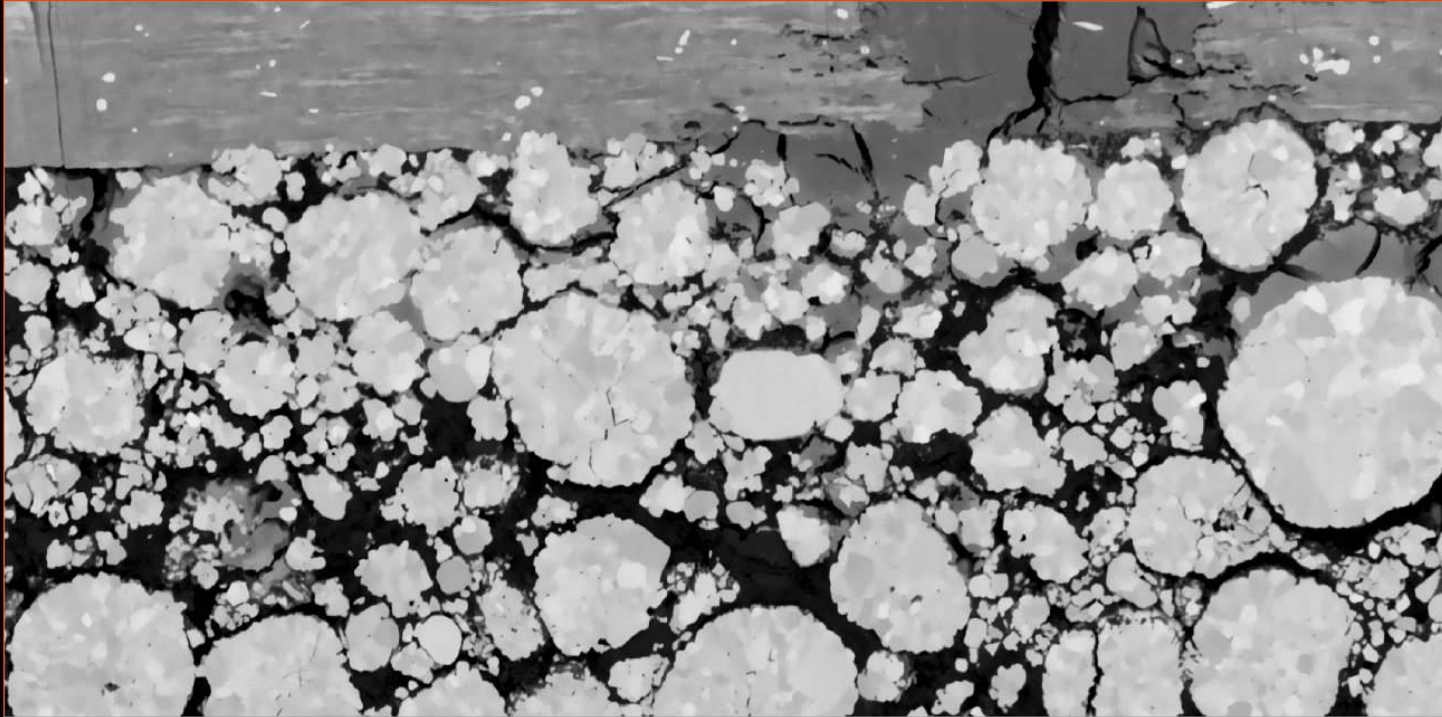
Sample:
Li-Ion battery electrode

Sample Courtesy: Johannes Schmalstieg (ISEA), Fabian Frie (ISEA), Joachim Mayer (GFE) RWTH, Aachen, Germany

Data acquired: Chengge Jiao, Thermo Fisher

Plasma Focus Ion Beam (FIB)

Helios G4 PFIB – Correlative workflow (μ CT-Dual Beam)



Avizo:

- Reconstruct the data
- Build the pore network
- Link with performance

Sample:

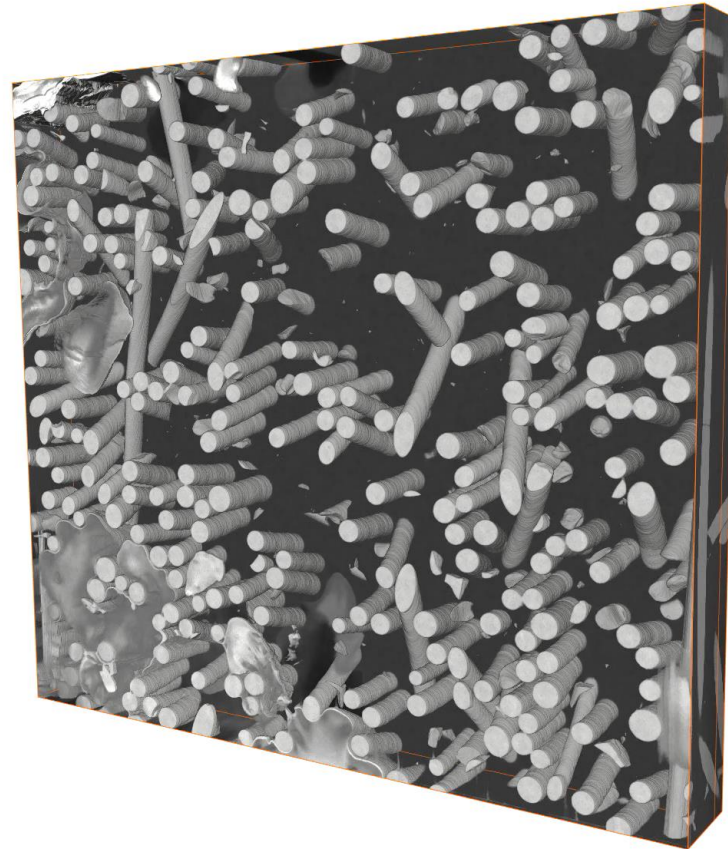
Li-Ion battery electrode

Sample Courtesy: Johannes Schmalstieg (ISEA), Fabian Frie (ISEA), Joachim Mayer (GFE) RWTH, Aachen, Germany

Data acquired: Chengge Jiao, Thermo Fisher

Helios 5 Hydra

Highest quality large volume 3D characterization - **Oxygen ions** for improved cut face quality in **Carbon-based materials**



200 μm

Sample: Car Oil Filter Casing
(polymer/glass fibre composite)

Data courtesy of Bart Winiarski, ThermoFisher

TEM Sample Preparation – Non-Biological Sample

Outline

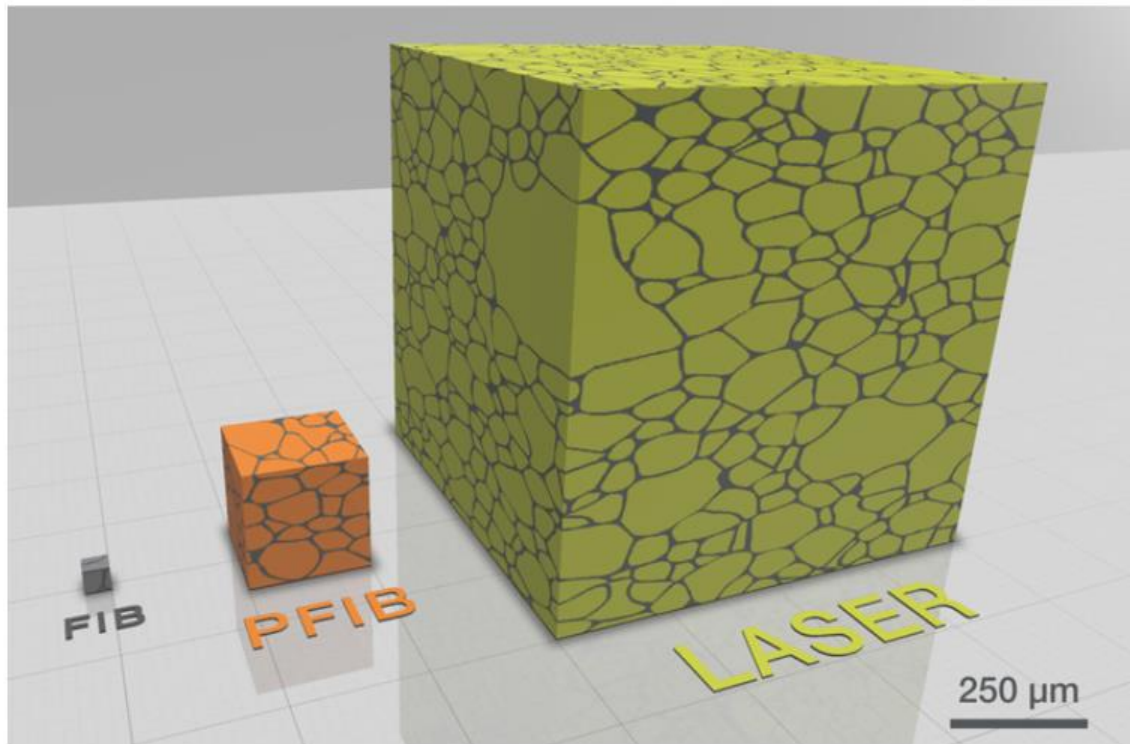
- Introduction
- Sample Preparation
 - Conventional Techniques
 - Focused Ion Beam Techniques
 - Ga ion
 - Plasma
 - Plasma + Laser
- Artifacts caused by bad sample preparations



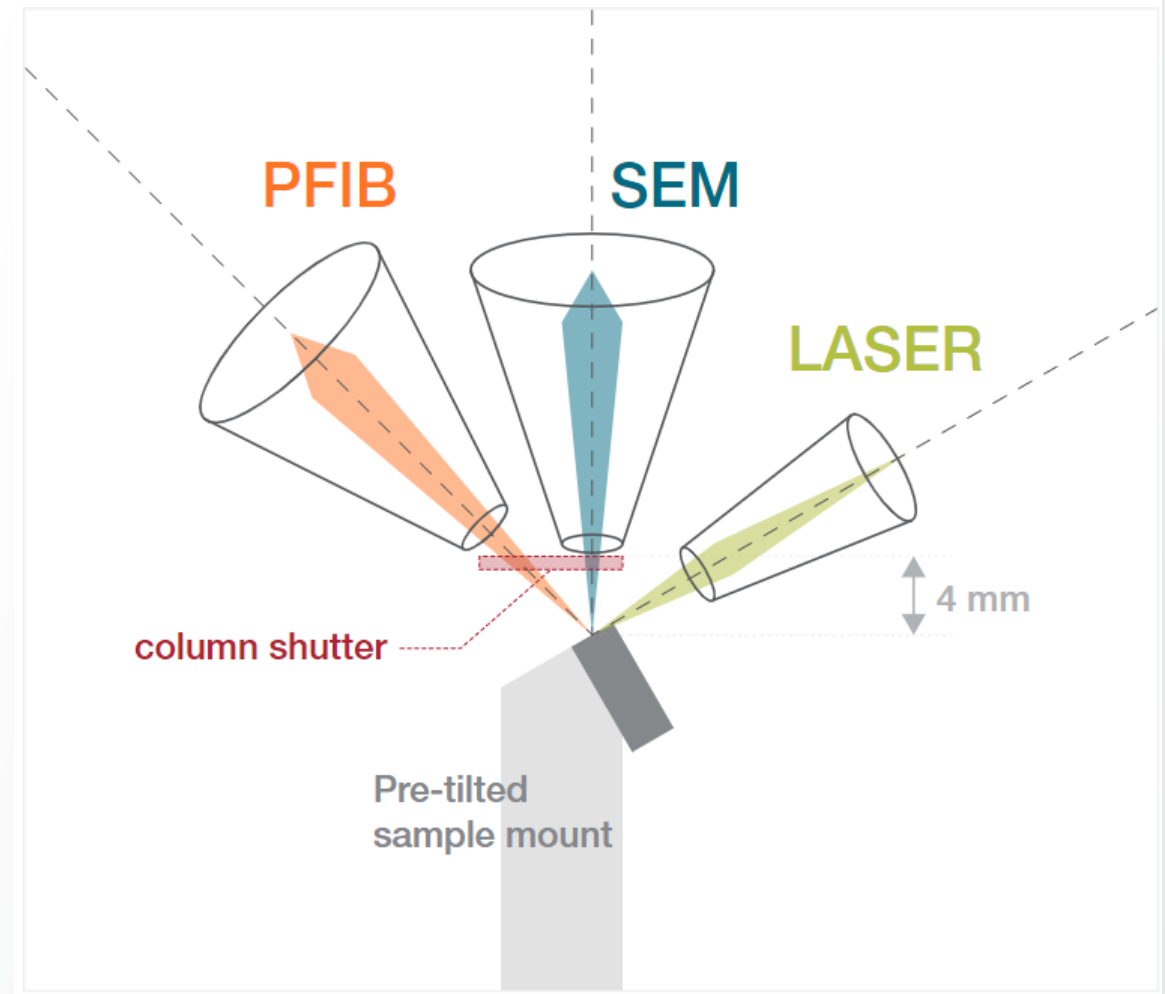
Helios 5 Laser PFIB

Helios 5 Laser Hydra System

Fast high-quality subsurface and 3D characterization at millimeter scale with nanometer resolution



Comparison of representative 3D volumes acquired within the same amount of time with FIB, Plasma FIB, and femtosecond laser.



Schematics of Helios 5 Laser Hydra. Three beams converging at a single coincident point allows fast switching between SEM imaging and laser processing, provides accurate and repeatable cut placement, increases throughput, and enables 3D characterization.

Helios 5 Laser Plasma FIB

Laser ablation for high-quality cross-sectioning of auto-body paints

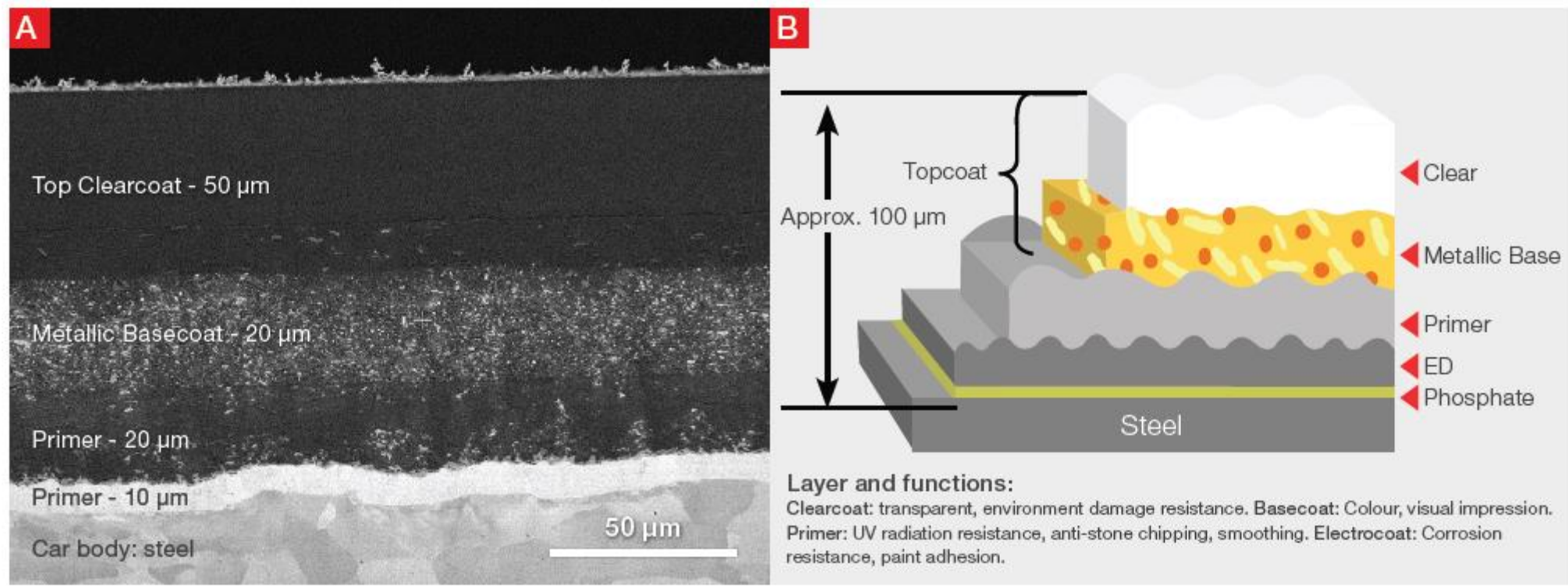
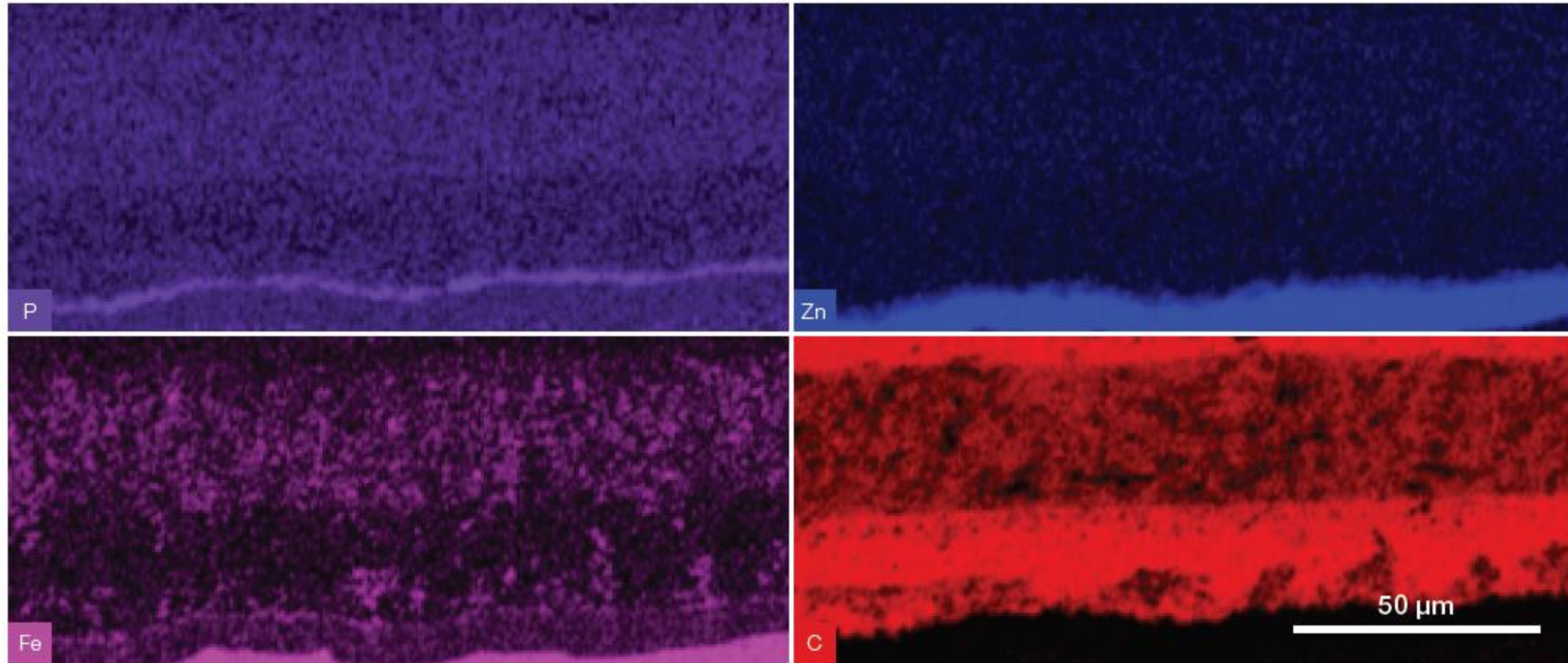


Figure 1. A) SEM backscattered electron image of an auto body coating cross-section. B) Typical four-layer automotive paint structure.

The schematic drawing is modified, with permission, from Akafuah, N, Poozesh, S, et al. Evolution of the Automotive Body Coating Process—
A Review. *Coatings*, 6(2), 24. 2016. doi:10.3390/coatings6020024

Helios 5 Laser Plasma FIB

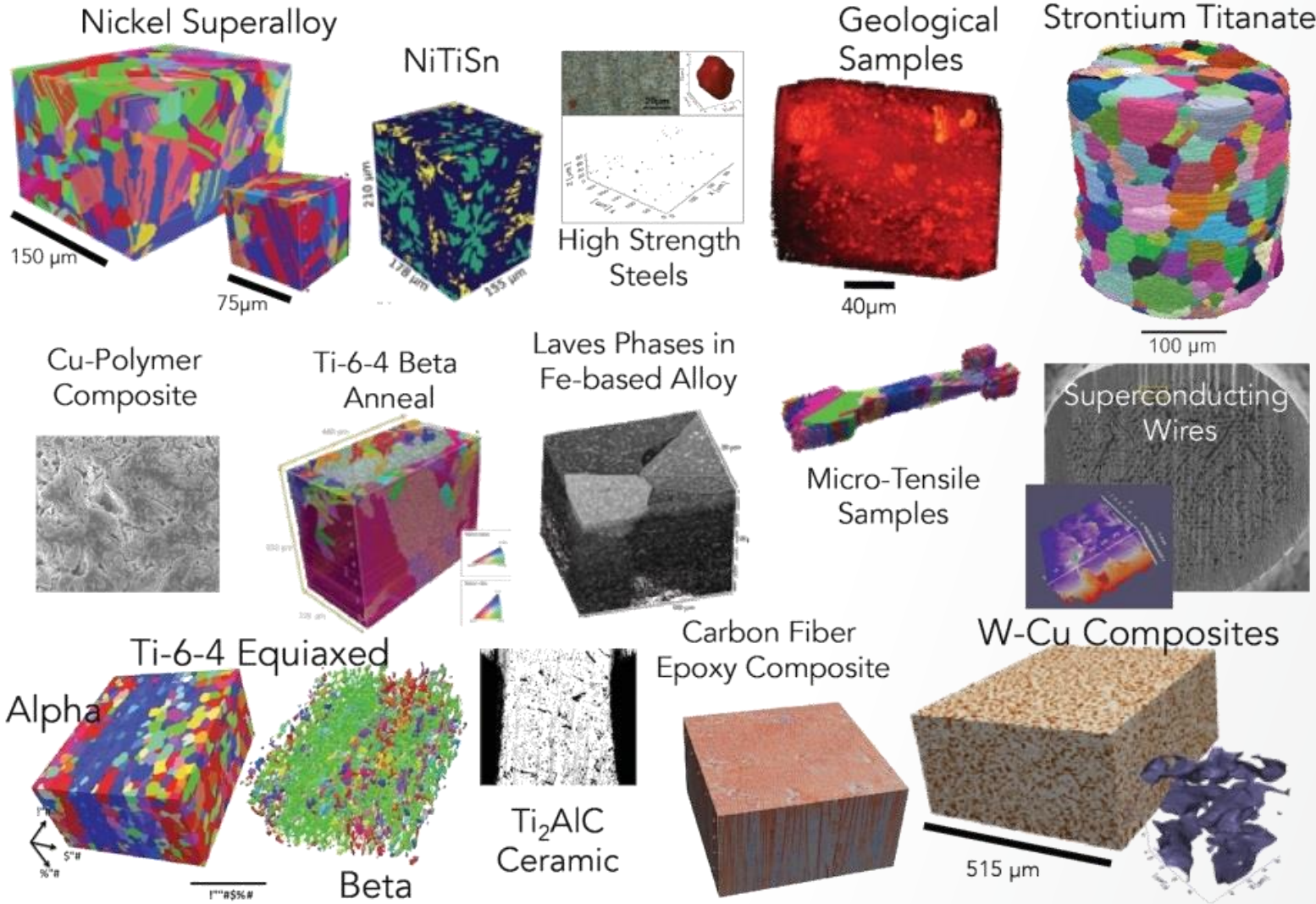
Laser ablation for high-quality cross-sectioning of auto-body paints



EDX elemental maps clearly correlate to the paint structure shown in the previous figure. Both cross-section preparation and imaging were performed using the Thermo Scientific Helios 5 Laser Plasma FIB. The cross-section was prepared using only the integrated in-chamber laser, without a PFIB clean up step. This demonstrates the high quality of femtosecond laser processing and enables the instrument to maintain high-throughput characterization.

Helios 5 Laser PFIB – Early adopters

Numerous examples and publications on metals, ceramics, composites, geoscience



Data courtesy: UC Santa Barbara

TEM Sample Preparation – Non-Biological Sample

Outline

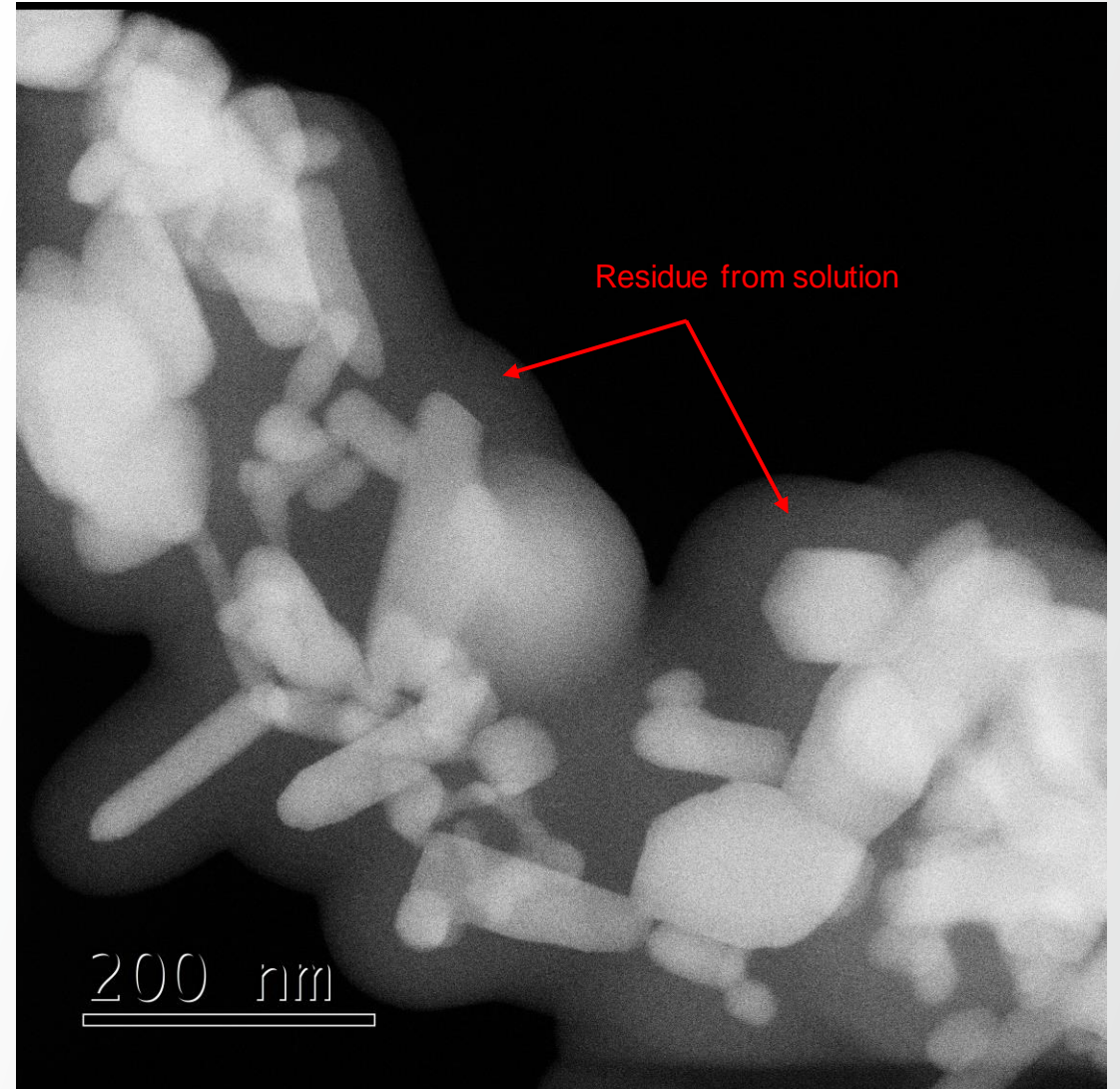
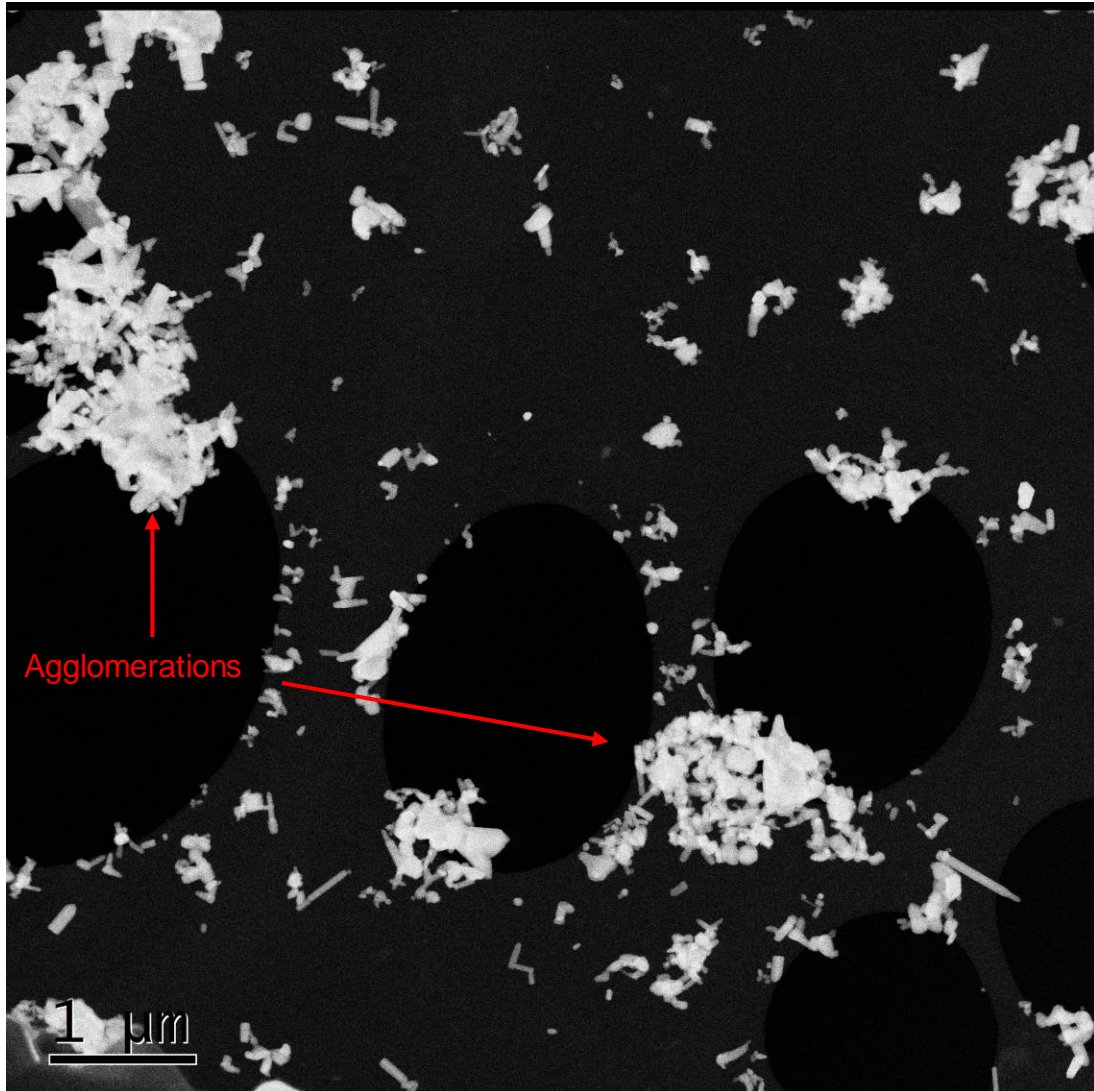
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Talos F200X

Examples

Powder Agglomerations and Residue from Solution



Examples

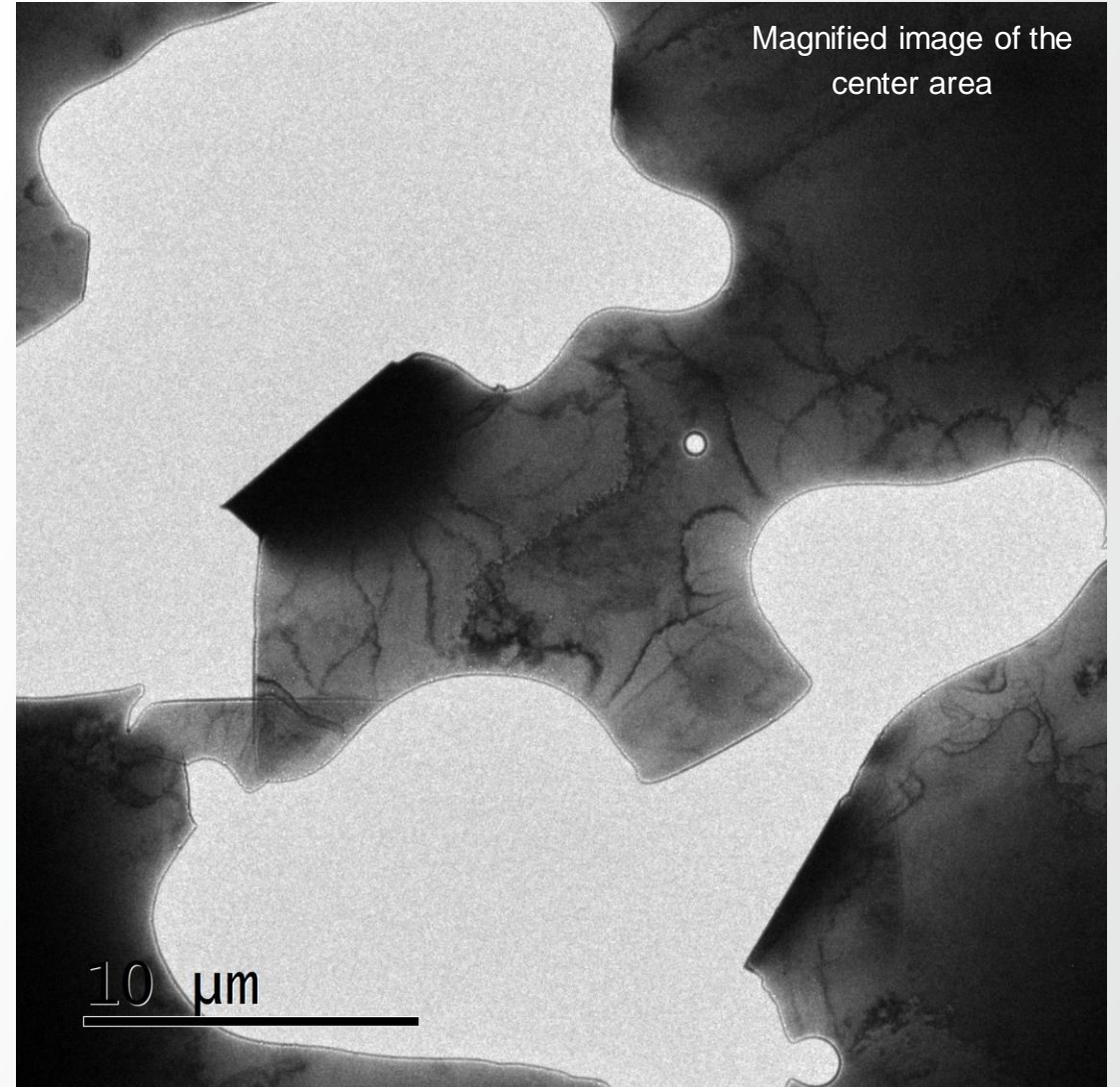
Ion Milling Sample

The ion milled only at the center of the sample without forming an electron transparent area

Where the thinnest part should present



100 μm

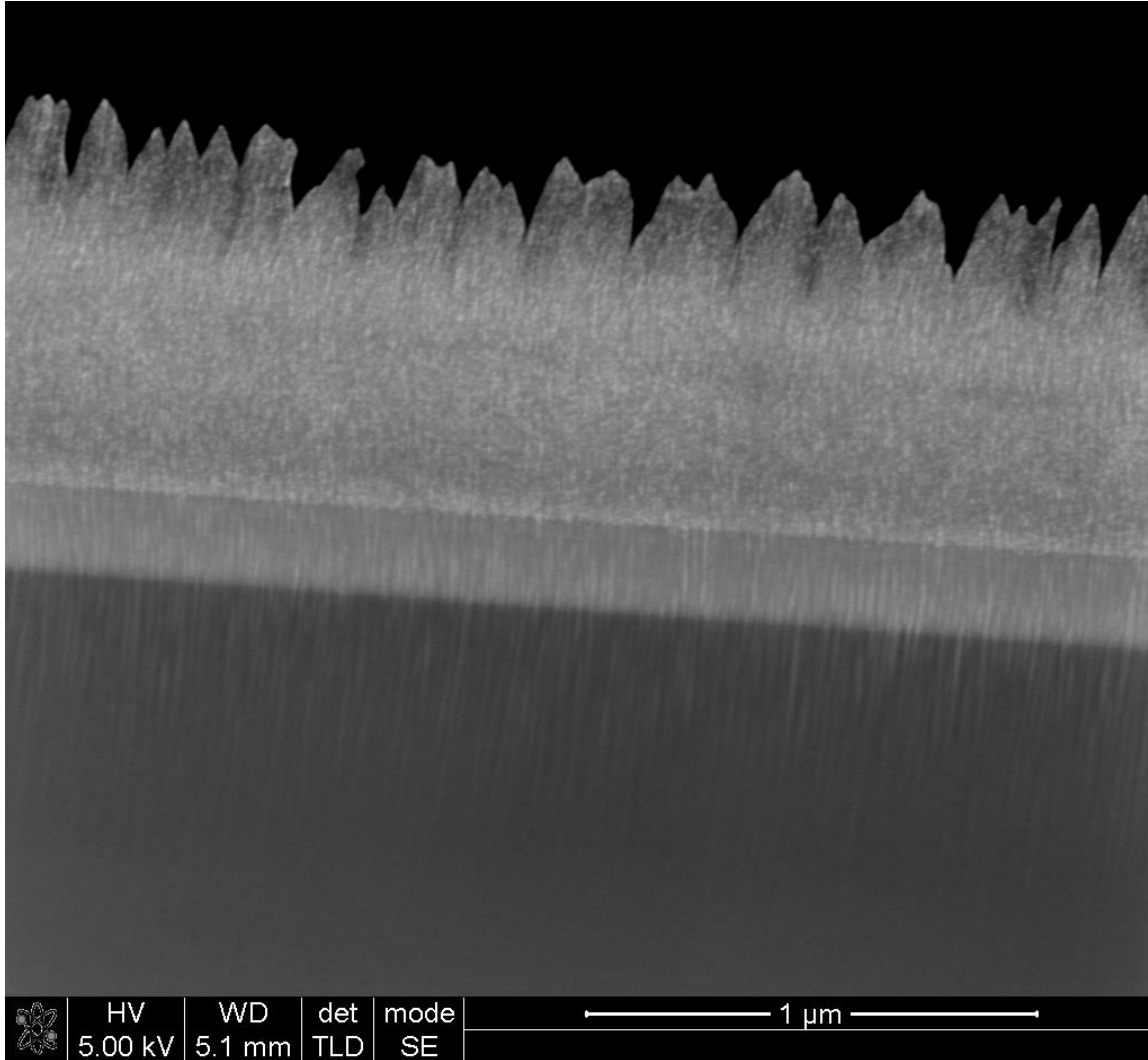


Magnified image of the center area

10 μm

Examples

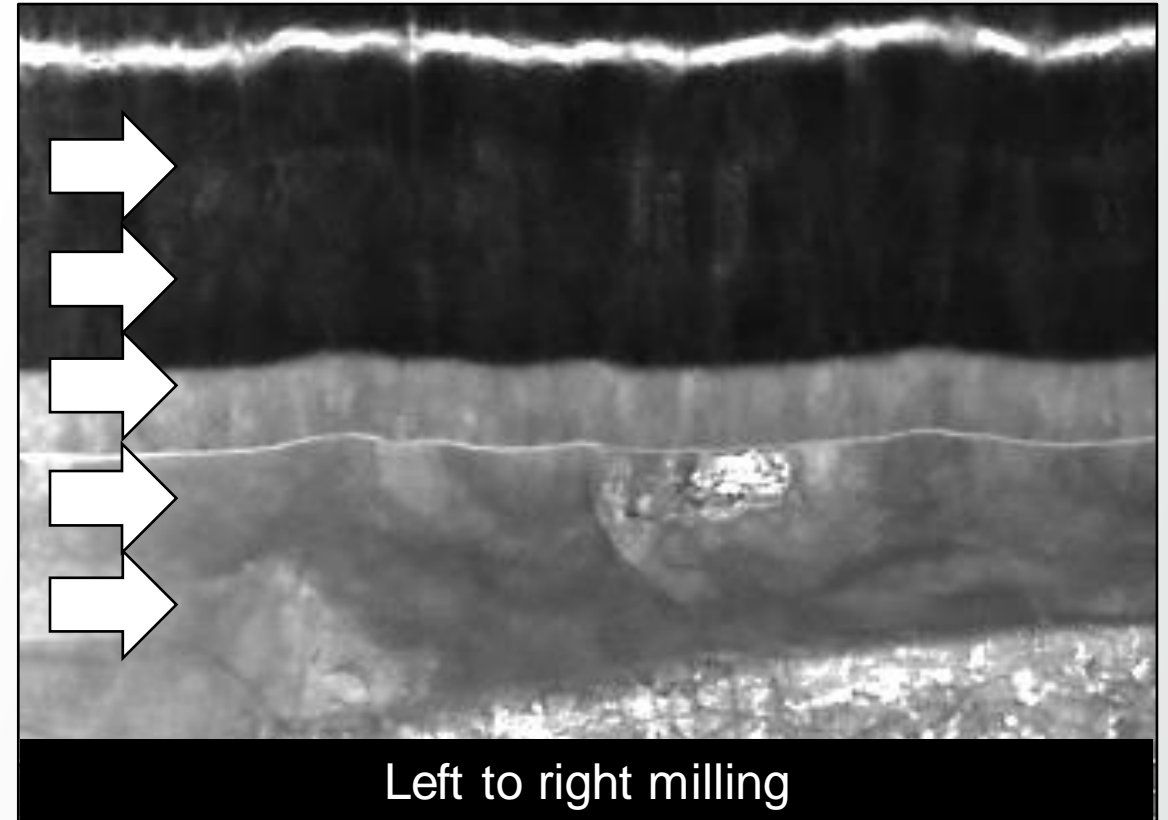
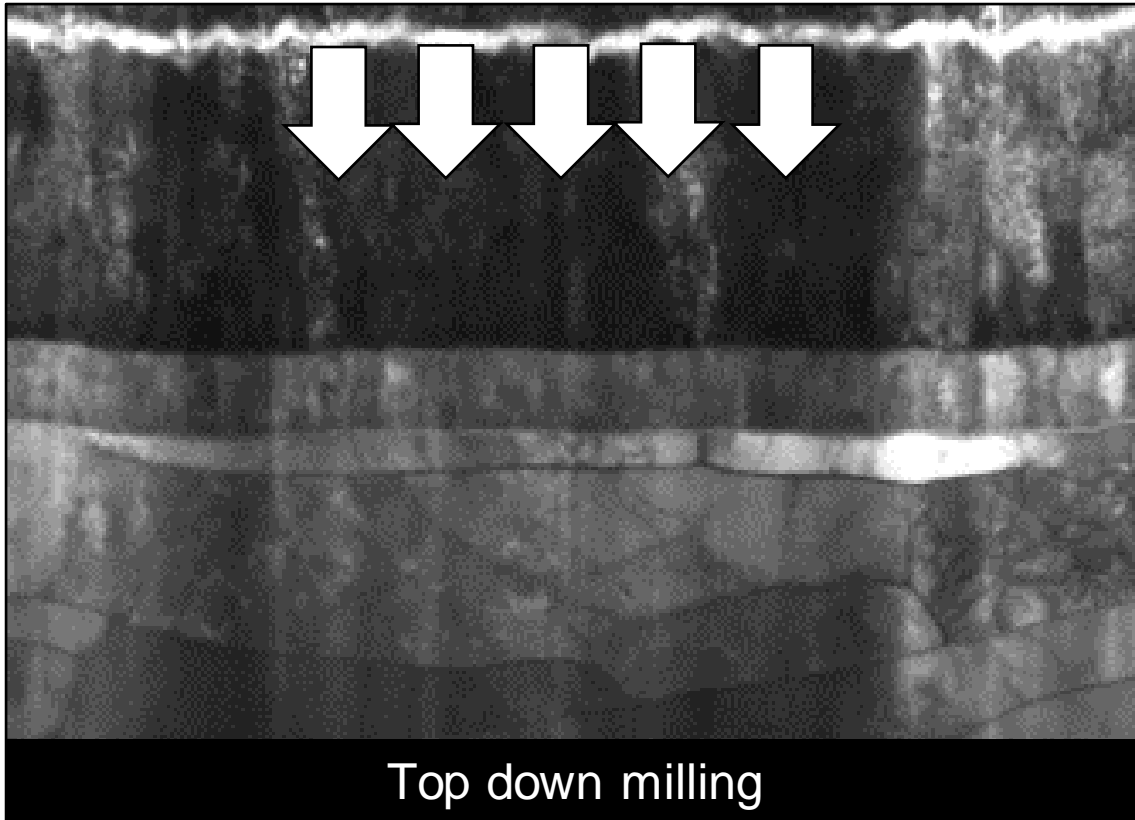
FIB Lamella, Curtaining Effect



- As seen in the image to the left, curtaining artifacts induced by the granular Pt microstructure can obscure the features below and produce less than optimal images

Examples

FIB Lamella, Curtaining Effect: Change Milling Orientation: Easy Lift

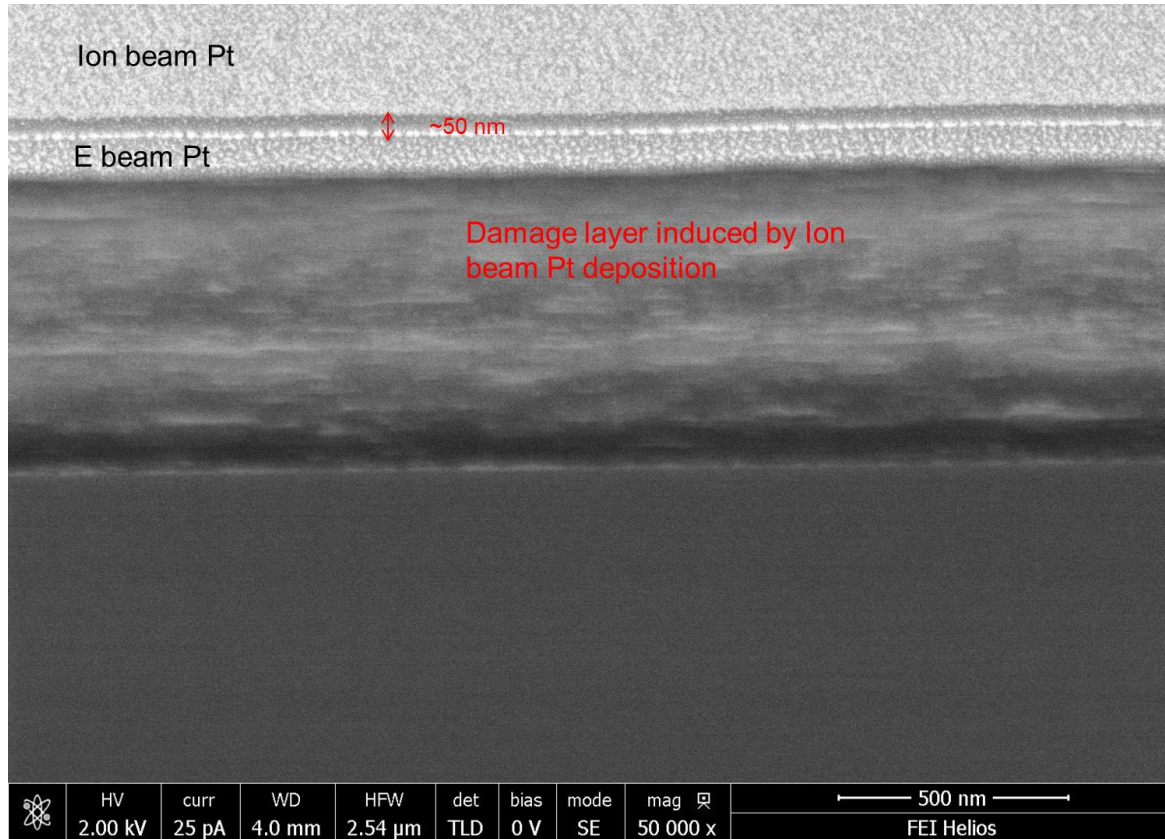


Change of orientation results in:

- More uniform lamella's without curtaining
- Avoiding smearing effects
- Preserve interfaces for measuring critical dimensions

Examples

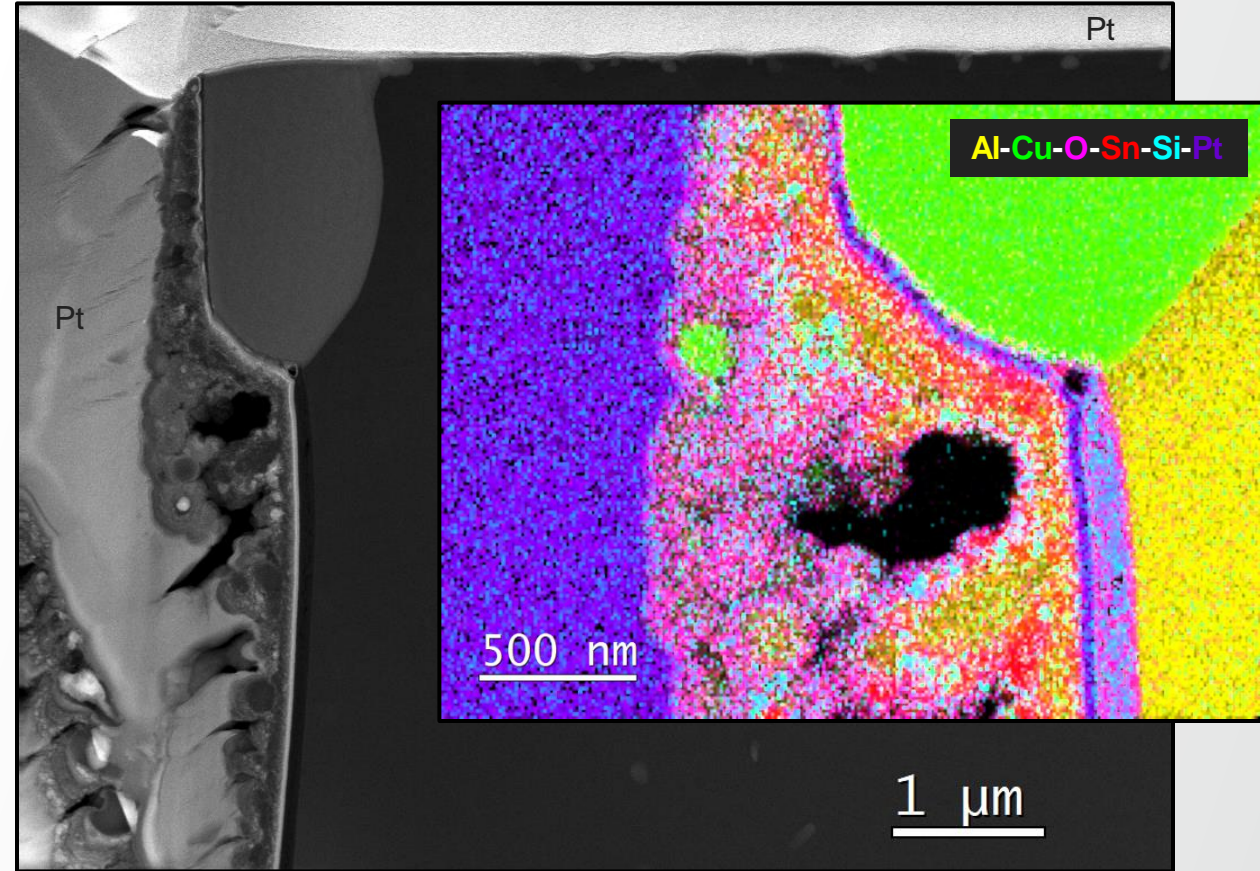
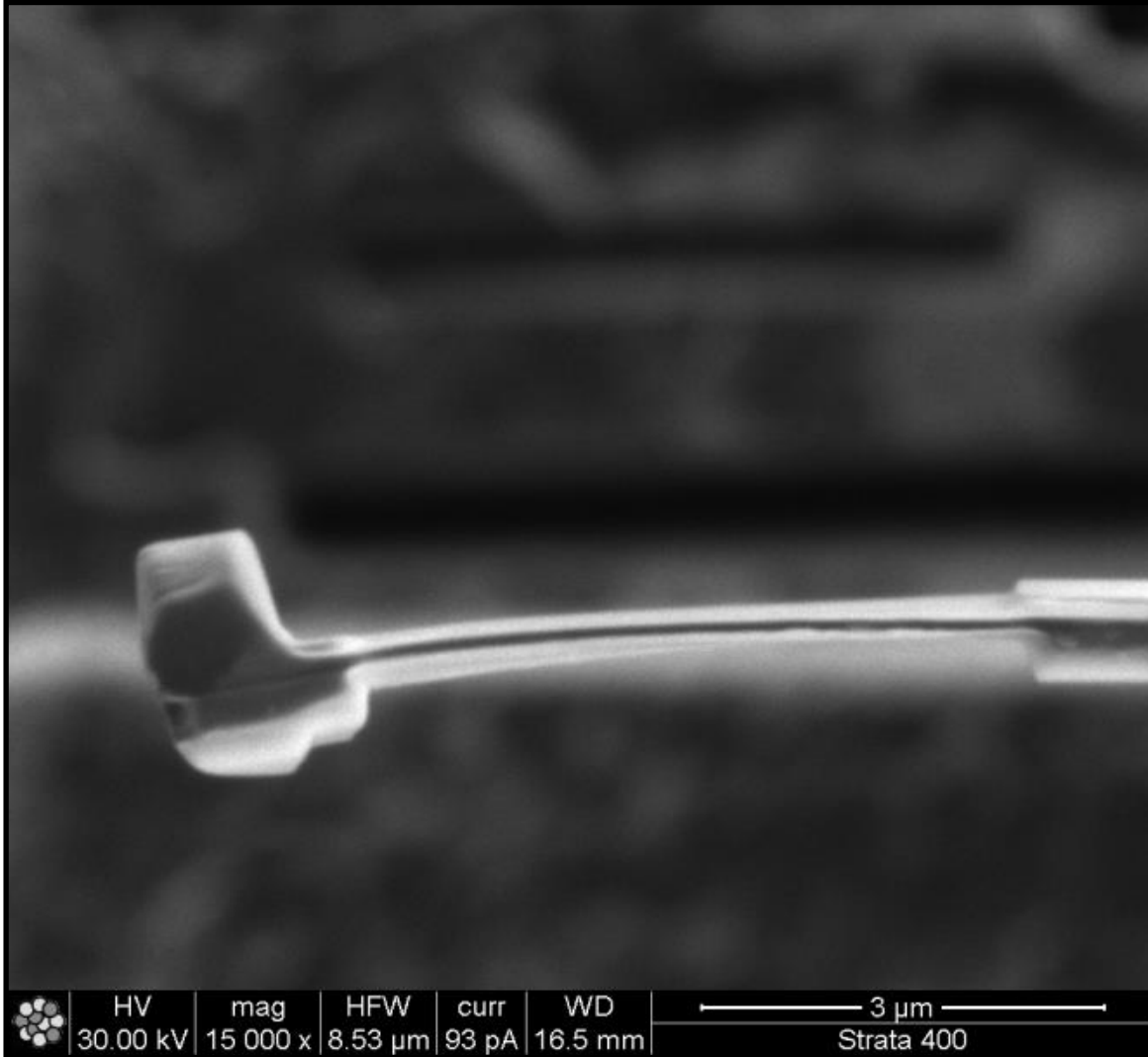
Damage Layer Induced by Ion Beam



- Electron beam deposition is recommended when the top surface of the bulk sample is of interest
- Deposition using the ion beam perpendicular to the sample surface will cause a layer of damage (~ 50nm depending on ion beam-material interactions) at the beginning of the deposition process

Examples

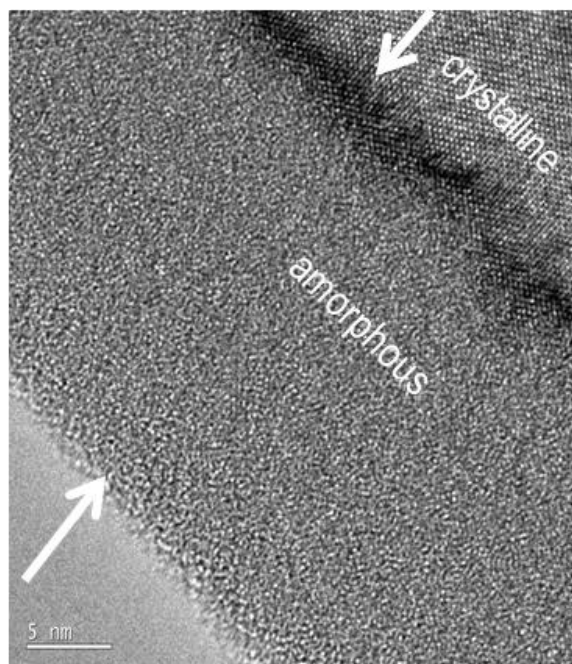
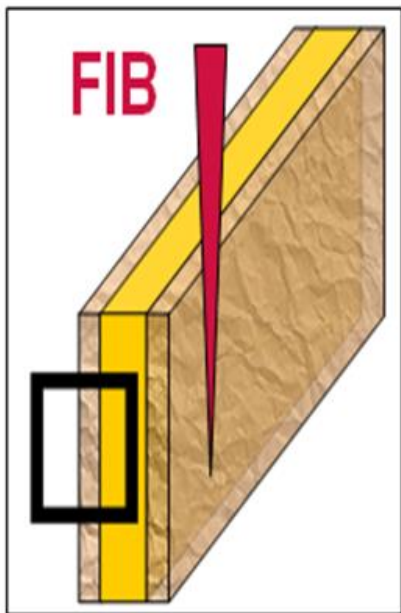
Sample Bending and Pt inclusion



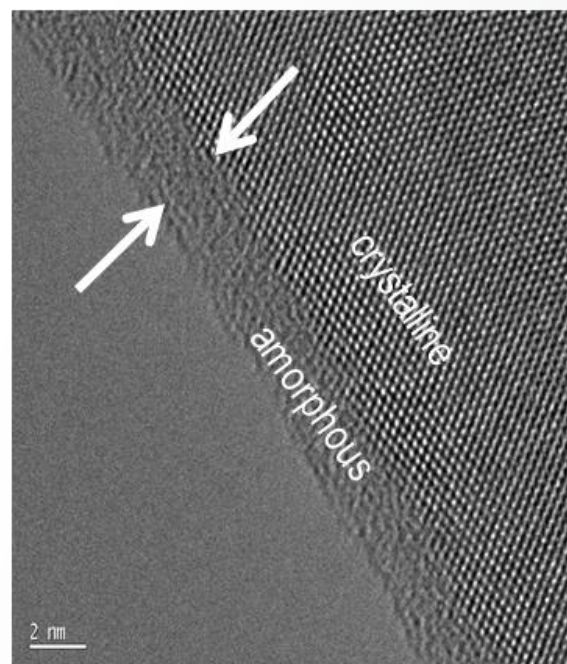
Examples

Amorphous Layer: Low kV Polishing

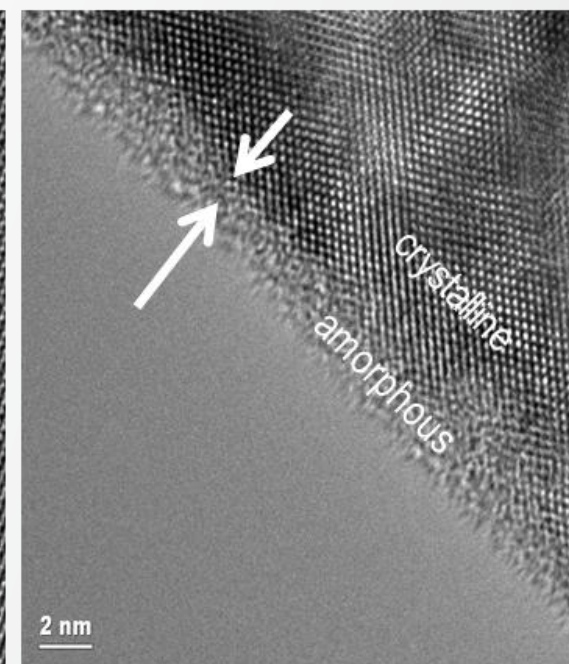
- ~ 20-25 nm of amorphous damage can be induced by the 30 kV ion milling on both sides of the lamella



30 kV
~ 21 nm each side



5 kV
~ 2 nm each side



2 kV
~ 0.5 – 1.5 nm

Thank you

